HD153035F 56-Mbps Read Channel

OHITACHI

rev. 1 Oct. 1993

Description

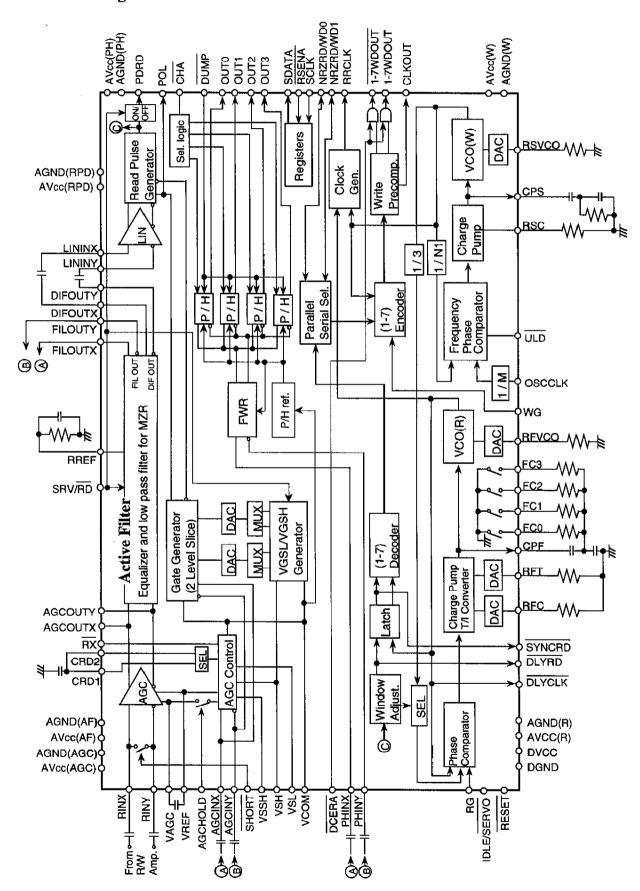
The HD153035F is a 56 Mbps 1-7 ENDEC data separator with built-in read pulse detector, active filter, frequency synthesizer and synchronizer, developed for use in magnetic disk drives. In read mode the HD153035 F decodes the read wave form output from the read/write amplifier into an NRZ signal. In write mode it encodes the NRZ signal output from the controller into a 1-7 RLL code.

Features

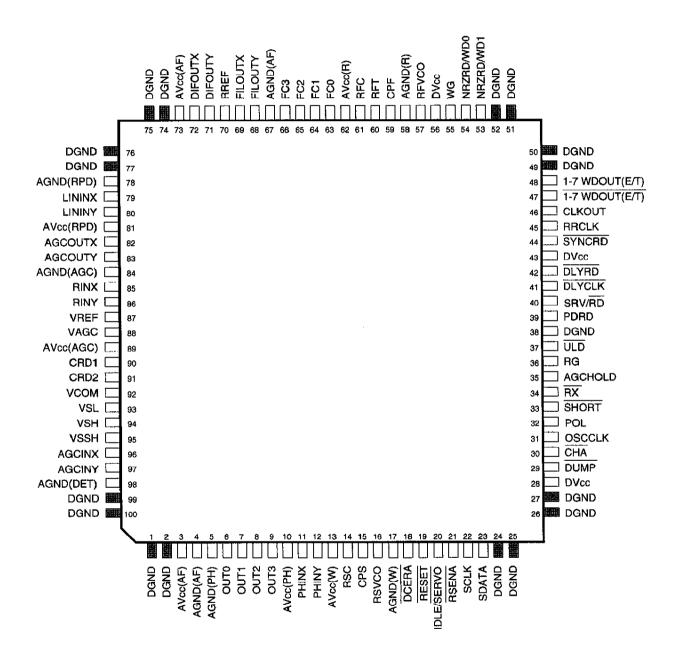
- Maximum NRZ data transfer rate: 56Mbps.
- Data transfer clock frequency: 1.5 data transfer rate (84MHz maximum).
- Settings are micro-computer programmable.
- On-chip frequency synthesizer generates encode clock for writing (f MAX/fMIN = 3.98).
- Programmable window centering adjustment and window monitoring functions.
- User-selectable single zone recording or multiple zone recording options. The following are programmable for multiple zone recording: VCO center frequency (192 settings), loop Filter constant (2 settings), charge pump current levels (8 settings), T/I converter output current (8 settings), active filter cutoff frequency for servo and data modes (128 settings).
- Dual-mode phase detector compares both phase and frequency to ensure a wide capture range.
- Separate active filter 7-bit programmable cut-off frequencies.
- Two sets of 4-bit High and Low slice levels for reliable pulse detection.
- 1-7WDOUT outputs are selectable differential pseudo-ECL or TTL pair for high speed transfer without timing error.
- High-speed acquisition can be accomplished with highly stable reproduction by switching between normal-gain and high-gain modes, and by switching loop filter constants.

- VCO oscillation timing capacitor is built in for better noise immunity.
- PLL characteristic frequency and damping rate are defined without 2T-8T (1-7RLL) signal cycle.
- Built-in AGC amplifier for stable reproduction despite varying media and head characteristics.
- Gate generator eliminates incorrect read pulse problems that occur with time-domain filtering with appropriate slice-level setting.
- Head resolution can be increased without incorrect read pulse worries.
- AGC amplifier gain can be set to zero during writing.
- Built-in write phase compensation function with programmable delay time.
- Early or Late write pre-compensation amounts can be programmed independently.
- Built-in active filter with 7-bit programmable cutoff frequency.
- High speed data transfer inputs and outputs are done via complementary TTL output pairs.
- Hi-BiCMOS process achieves high speed with low power dissipation.
- Idle mode and power down functions.
- QFP-100 pin package suitable for compact surface mounting (resin size: 14mm x 14mm)
- Required only a single 5V supply.

2. Block diagram



3. Pin arrangement



(Top view)

4. Pin Functions

Pin Name	Pin No.	Туре	Function
RINX RINY	85 86	Differential input	Differential input lines for the signal read from the recording medium.
AGCOUTY AGCOUTY	82 83	Differential output	Differential output lines for monitor from the AGC amplifier. The outputs are open-emitter type and would need ext. $1\sim10K$ pulldowns.
CRD1	90	External component required	In reading the normal data, the charge /discharge current output line for the AGC output amplitude detector. Connected to pin 91 (CRD2).
CRD2	91	External component required	External capacitor is needed for AGC output amplitude detector. Connected to pin 90 (CRD1).
VCOM	92	External component required	Reference voltage output line for the AGC output amplitude detector and the Gate generator.
VSL	93	External component required	Voltage input line for setting the low slice level of AGC output amplitude detector. Corresponds to the discharge current threshold. Normally this level is set 67% of the VSH level.
VSH	94	External component required	Voltage input line for setting the high slice level of the AGC output amplitude detector. Corresponds to the charge current threshold
VSSH	95	External component required	Voltage input line for setting the fast attack(high gain) high slice voltage of the AGC output amplitude detector. Normally this level is set to 160% of the VSH level.
VREF	87	Monitor line	Monitor line for the AGC amplifier reference voltage.
VAGC	88	Monitor line	Monitor line for the AGC amplifier gain setting voltage.
FILOUTX FILOUTY	69 68	Differential output	Differential output line from Active Filter. Connect to AGCINX,Y and PHINX,Y through bypass capacitors.
DIFOUTX	72 71	Differential output	Differential output line from Active Filter. Connect to LININX,Y through bypass capacitors.
AGCINX AGCINY	96 97	Differen- tial input	Differential input lines to the AGC output amplitude detector. Connect to FILOUTX/Y outputs of the AF with bypass capacitors.
RREF	70	External component required	Connect to a resistor and a capacitor to set the reference current for the Active Filter's DAC.

Pin Name	Pin No.	Туре	Function			
SHORT	33	In (TTL)	When this terminal is 'L', RINX and RINY are shorted together.			
RX	34	In (TTL)	TTL-level input that switches the AGC loop on or off.			
			When RX signal turn Low to High, AGC gain starts	RX input	AGC loop	
			from maximum gain.	High	AGC loop closed.	
				Low	AGC loop open.	
AGCHOLD	35	In (TTL)	TTL-Level input that locks the AGC amplifier gain. When AGCHOLD goes High the gain is locked at its immediately preceding value.			
SRV/RD	40	In(TTL)	"H":Servo Mode, "L":Read Mode. In the servo mode , "CFCB" register set the A/F's cutoff frequency and VGSLB register set the gate slice low level. In the read mode , "CFCA" register set the A/F's cutoff frequency and VGSLA register set the gate lowslice level.			
PHINX PHINY	11 12	1n	Differential inputs for the servo Peak/Hold circuit.			
OUT0~ OUT3	6,7, 8,9	External component required	Connect to external capacitors for servo peak/hold.			
CHA	30	In (TTL)	Input pin of the control signal of Peak/hold circuit(TTL level) Position signal is sampled by CHA="L"			
DUMP	29	In (TTL)	Input pin of the discharge control signal of Peak/Hold circuit. TTL level, DUMP="L" is for discharge.			
LININX LININY	79 80	Differen- tial input	Differential input lines for the zero-crossing comparator. Normally connect to DIFOUTX/Y of the active filter with bypass capacitors.			
PDRD	39	Out(TTL)	Output line for the data read from disk as reshaped into digital data by the read pulse detector. When SRV/RD(pin40) goes high, PDRD outputs read data pulse. When SRV/RD goes low, PDRD is disable.			
POL	32	Out(TTL)	Output pin of the polarity sign	al for read signa	al from disk drive.	
RFVCO	57	External component required	Connect to a resistor to set the center frequency of the VCO in the decode clock generator's VFO.			
RFC	61	External component required	Connect a resistor to set the charge pump output current for the decode clock generator's VFO. The charge pump current level is set by GAC[5:3] and CPO[4:0] registers.			

Pin Name	Pin No.	Туре	Function					
RFT	60	External component required	Connect a resistor to set the T/I converter's sampling feedback gain to 1(nominal). The T/I converter's output current is determined by this resistor, and registers VFC[4:0] & GAC[2:0] & TIO[4:0].					
CPF	59	External component required	Current output to the external loop filter.					
FC0 FC1 FC2	63 64 65	External component required	Connect to a loop filter resistor to set the attenuation ζ of the Each line is grounded through an MOS switch is selected by					
FC3	66	•	gain mode and bit 6 of	_	-		in	
			Bit 6 of register GAC		FC0	FC1	FC2	FC3
			" 0 " -	High Normal	ON	ON OFF	OFF OFF	OFF
				High	OFF	OFF	ON	OFF ON
			"1" -	Normal	OFF	OFF	ON	OFF
DLYCLK	41	Out(TTL)	Monitor pin(TTL level) for Window adjustment. This pin allows the VCO clock signal output by the PLL circuit to be monitored. Contact Hitachi,Ltd. for special instructions if use of this function is required.					
DLYRD	42	Out(TTL)	Monitor pin(TTL level) read data signal outp monitored. Contact Hi	for Window adju	stment.	This p	in allo	ws the
			function is required.					
SYNCRD	44	Out(TTL)	Monitor pin(TTL level) for Window adjustment. This pin outputs the read data outputs the read data input to the PLL block latched by the VCO clock. Contact Hitachi, Ltd. for the special instructions if use of this function is required.					
RSVCO	16	External component required	Connect a resistor to set the center frequency of the VCO in the encode clock generator's frequency synthesizer.					
CPS	15	External component required	Current output to an external loop filter.					

Pin Name	Pin No.	Туре	Function
RSC	14	External component required	Connect a resistor to set the charge pump output current for the encode clock generator's frequency synthesizer.
OSCCLK (Oscillator clock)	31	In(TTL)	Clock synthesizer's reference clock input. The frequency synthesizer generates encode clock frequencies from the input on this line. Data writing is synchronized with the encode clock. When not reading data, the decode clock generator's VFO is also synchronized with frequency 1.5 times the data transfer rate.
ULD (Unlock detect)	37	Out(TTL)	Error output from the encode clock generator's frequency synthesizer. ULD goes low to indicate that the PLL in the encode clock generator's frequency synthesizer has lost lock. The disk controller should immediately halt the write operation. Data must be written again from the beginning.
WG	55	In(TTL)	Write gate signal input. Set this pin high during writing.
NRZRD/WD1	53	In/Out (TTL)	I/O pin of NRZ signal. This pin is effective only in the case of parallel transferring. NRZ Data select bit 7 of register(\$h8) controls parallel/serial. (When this bit is " H", NRZ mode is parallel)
NRZRD/WD0	54	In/Out (TTL)	I/O pin of NRZ signal. In the serial transfer mode, only this pin is effective. NRZ Data select bit 7 of register(\$h8) controls parallel/serial. (When this bit is "L", NRZ mode is serial)
RRCLK	45	Out(TTL)	Read reference clock output(TTL level). At read time, this pin provides a clock which is synchronized with the converted NRZRD signal. This controller should read NRZRD by this clock. Other than read mode, reference clock is provided to disk controller.
1-7WDOUT 1-7WDOUT (Write Data outputs)	48 47	Out (TTL/ECL)	1-7 RLL Write Data Differential Output. Pseudo ECL/TTL are available by bit 6 of register"\$hD". When this bit is "H", these outputs are TTL. When this bit is "L", these outputs are ECL.These pin provide the 1-7WDOUT write data that goes to the Read/Write amplifier after the write pre-compensation. When WG goes high, 1-7WDOUT pin are output mode.
CLKOUT	46	Out(TTL)	This clock is for the external write pre-compensation in the Write mode. This clock(TTL level) is synchronized with 1-7WD.
DCERA	18	In(TTL)	Input pin for the DC erase. When this pin is "L", 1-7WDOUT (pin#4 8) is "L" and 1-7WDOUT (pin#47) is "H".
RESET	19	ln(TTL)	Low input initializes internal circuits. Drive this line low at power-up. Low input also locks the two built-in VCOs to their center frequencies. Keep this line high during normal operation.
RSENA	21	In(TTL)	This active low input selects the device and enables the serial port.
			•

Pin Name	Pin No.	Туре	Function
SCLK	22	In(TTL)	This is the serial clock sent in by the hard disk controller or other ASIC device. When the serial port is not enabled, this clock line should be driven low. For either read or write transfer, a 16 clock burst is required for proper operation. Data is latched in during write or sent out during read at the rising edge of the SCLK.
SDATA	23	In/Out (TTL)	Data is transmitted in 16-bit packet MSB first. The first 2 bits determine the read or write mode, the next bit is "Don't Care", the next 4 bits are for the register address, followed by 1 "Don't Care" bit, then the last 8 bits are for the Write or Read Data.
IDLE/SER\	/O 20	in(TTL)	The input is used in combination with the two Mode bits in the PCN register to reduce power consumption in the Idle mode. When PCN= 00, device is in the R/W normal mode, all circuits are ON. When PCN = 11, device is in the Sleep mode, all circuits are OFF except the I/O and logic. When PCN = 10, then depending on the logic level of the IDLE/SERVO pin; if it is High, then chip is in the Idle mode and all circuits are OFF except for the I/O, logic, and the bias CKT's; if it is Low, then the device is in the Servo mode and the I/O, logic, bias CKT's, AGC, active filter, Read Pulse Detector, and Peak/Hold will be ON with only the RD PLL and the WR PLL being OFF.
DVcc	28, 43, 56	Power	Digital Vcc power supply.
DGND	1, 2, 24,25,26, 27, 38, 49, 50, 51, 52, 74, 75, 76, 77, 99,100	Ground	Digital ground.
AVcc(AGC) 89	Power	Analog Vcc power supply for AGC.
AGND(AG	C) 84	Ground	Analog ground for AGC.
AGND(DE	Γ) 98	Ground	Analog ground for AGC control circuit
AVcc(AF)	3, 73	Power	Analog Vcc power supplies for active filter.
AGND(AF)	4, 67	Ground	Analog ground for active filter.
AVcc(RPD)) 81	Power	Analog Vcc power supply for read pulse detector.
AGND(RPI	D) 78	Ground	Analog ground for read pulse detector.
AVcc(PH)	10	Power	Analog Vcc power supply for peak hold.
AGND(PH)	5	Ground	Analog ground for peak hold.
AVcc(R)	62	Power	Analog Vcc power supply for synchronizer.
AGND(R)	58	Ground	Analog ground for synchronizer.
AVcc(W)	13	Power	Analog Vcc power supply for synthesizer.
AGND(W)	17	Ground	Analog ground for synthesizer.
			

5. Registers

The HD153035F has 16 addressable 8-bits registers that control the center frequency of the decode clock generator's VFO and the frequency of the encode clock generator's frequency synthesizer, control the synthesizer's gain, control the read data pulse

width and its polarity, control the synchronizer's gain and offset, adjust the decode window, apply the early/late write precompensation, control the prescaling value, adjust the active filter's cut-off frequency, and controls various functions.

Address register value			Name	Abbreviation	
0	0	0	0	VCO center frequency control register	VFC register
0	0	0	1	RD-PLL Gain control register Synchronizer loop filter gain control bit. Synthesizer operating mode control bit	GAC register RFCA bit SPSYNT bit
0	0	1	0	RD-PLL Charge Pump Offset control register Write pre-compensation delay control register (L)	CPO register WPL register
0	0	1	1	RD-PLL T/I offset control register Write precompensation delay control register (S)	TIO register WPS register
0	1	0	0	Window adjustment register (0.67ns typ. /step) Window fine adjustment register(0.25ns typ. /step)	WAJ register WFA register
0	1	0	1	AGC Mode control bit (FAST / SLOW) Read data (PDRD) polarity control register Read data (PDRD) pulse width control register WR-PLL Gain control register	AGS bit RDSEL register PW register SGC register
0	1	1	0	Prescaler of WR-PLL control register	PSC register
0	1	1	1	AF cut-off frequency control register (for Read)	CFCA register
1	0	0	0	NRZ Data 1bit - serial / 2-bit parallel select bit AF cut-off frequency control register (for Servo)	NRZM bit CFCB register
1	0	0	1	Unlock detect gain control register (for WR-PLL) Boost level control register	ULD register BLC register
1	0	1	0	Boost enable bit at servo mode High pass filter cut-off frequency control register (for Read)	SRVBE bit HPCA register
1	0	1	1	High pass filter cut-off frequency control register (for Servo)	HPCB register
1	1	0	0	Gate generator's High-slice level control register (for Read) Gate generator's Low-slice level control register (for Read)	VGSHA register VGSLA register
1	1	0	1	1-7 WDOUT output type control bit (ECL / TTL) Write pre-compensation delay control register (E) Write pre-compensation delay control register (N)	WDM bit WPE register WPN register
1	1	1	0	AGCOUT enable control bit Power management control register Gate generator's Low-slice level control register (forServo)	AOE bit PCN register VGSLB register
1	1	1	1	Test Mode control register	MDC register

6. Register Descriptions

D5

D6

VCO Center Frequency Control register (VFC)

Address \$h0 (at write = "C0" hex, at read = "80" hex),

VFC Register

MSB

LSB

D2

D1

D0

D3

VFC register is 8 bits long.

D4

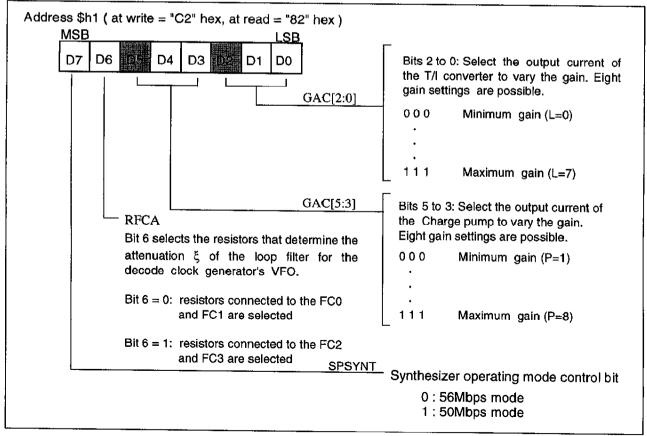
This register is used in multiple-zone recording to set the center frequency of the decode clock generator's VCO, the T/I converter's reference current, and the oscillation frequency of the encode clock generator's frequency synthesizer. Bit D7 is cleared when reset pin is asserted.

Resistors connected to the RFVCO and RSVCO lines set these values for the minimum data transfer rate. The VFC register raises these values in step of 1.56%, permitting 192 settings up to a maximum transfer rate 3.98 times of the minimum rate.

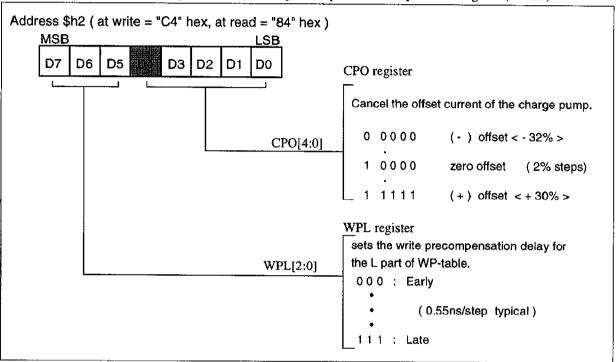
0 1 0 0 0 0 0 0 Minimum transfer rate (reference rate)

1 1 1 1 1 1 1 1 Maximum transfer rate (3.98 times speed)

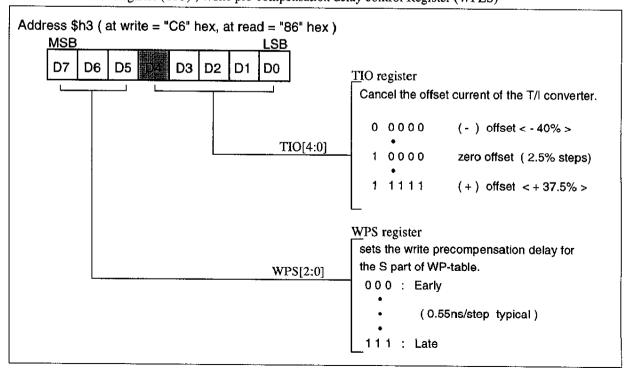
Gain Control Register (GAC) = RFCA, GAC[5:0] for Read PLL synchronizer



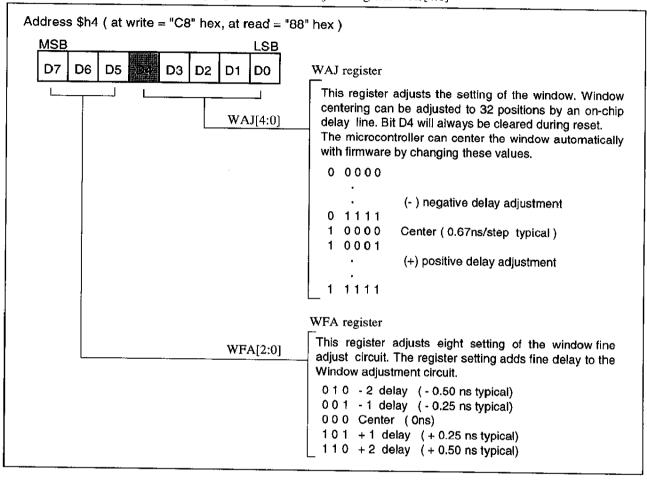
Charge Pump Offset Control Register (CPO), Write pre-compensation delay control Register (WPLL)



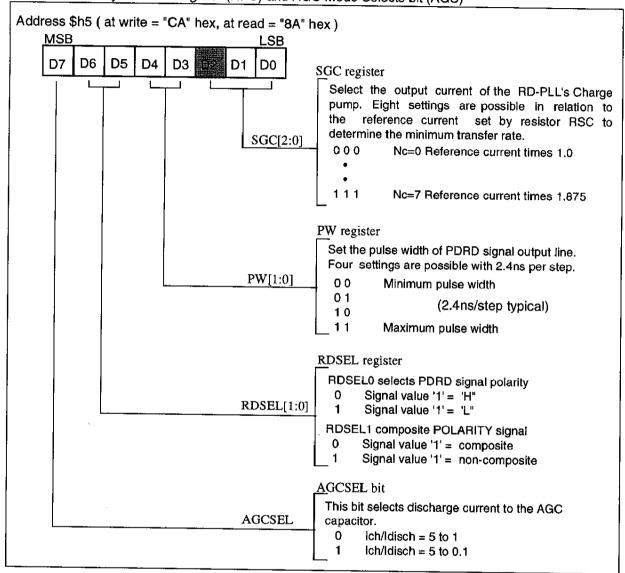
T/I Offset Control Register (TIO), Write pre-compensation delay control Register (WPLS)

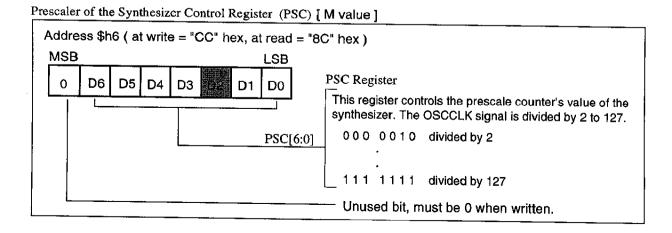


Window Fine Adjust Register WFA[2:0] and Window Adjust Register WAJ[4:0]

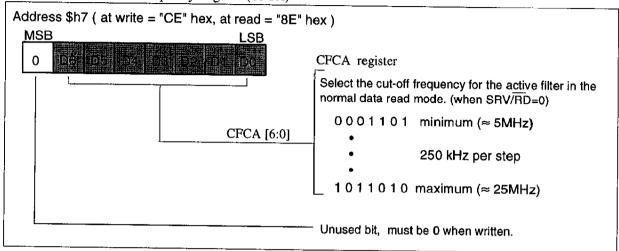


RD-PLL Gain Control Register (SGC), Read data Pulse Width Control Register (PW), Read data Polarity Control Register (RPC) and AGC Mode Selects bit (AGS)

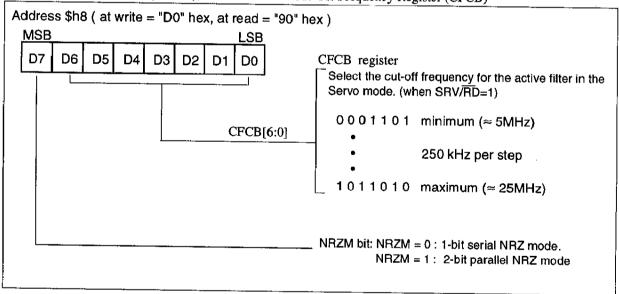




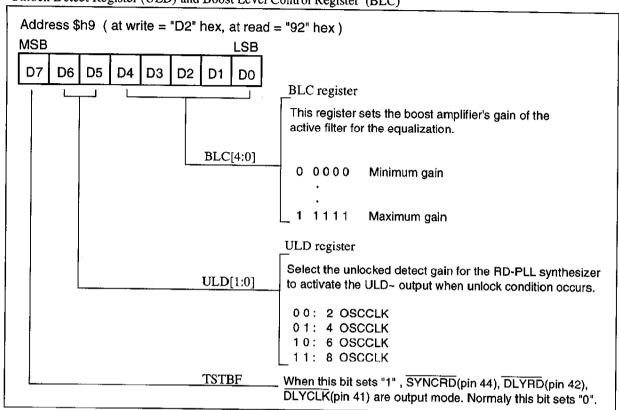
Read Mode AF Cut-Off Frequency Register (CFCA)

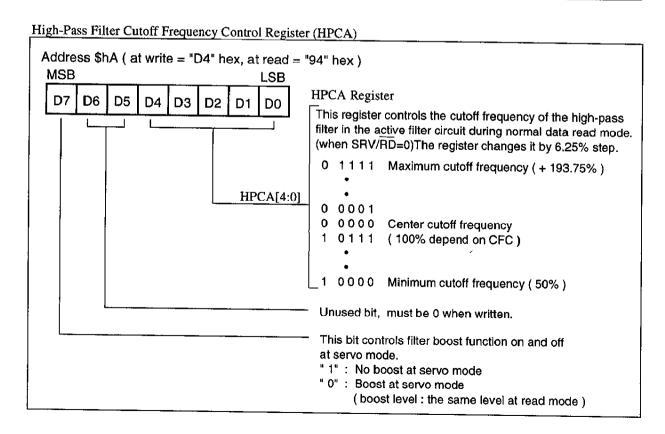


NRZ Data mode select bit (NRZM), Servo Mode AF Cut-Off Frequency Register (CFCB)

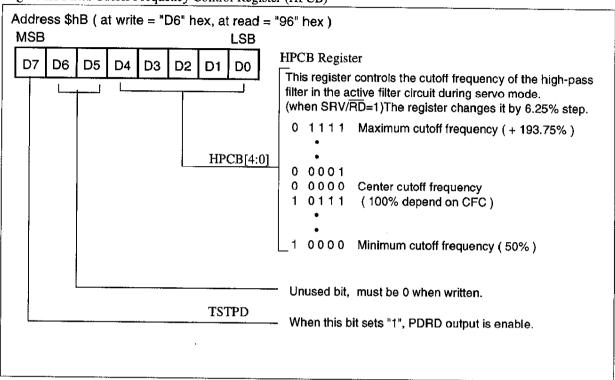


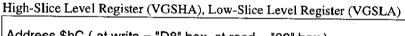
Unlock Detect Register (ULD) and Boost Level Control Register (BLC)

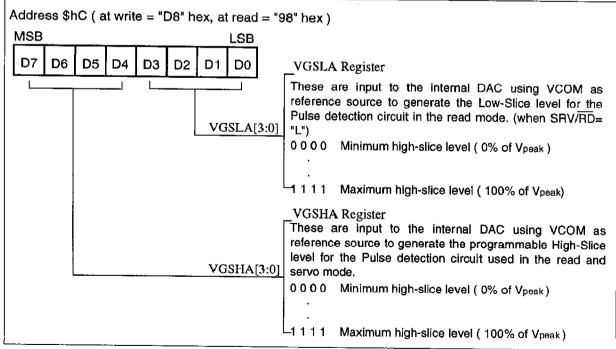




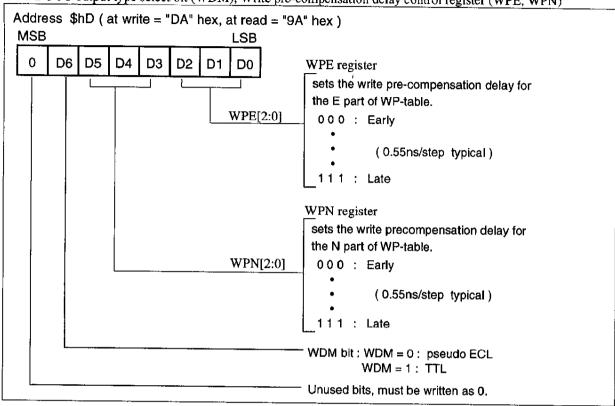
High-Pass Filter Cutoff Frequency Control Register (HPCB)

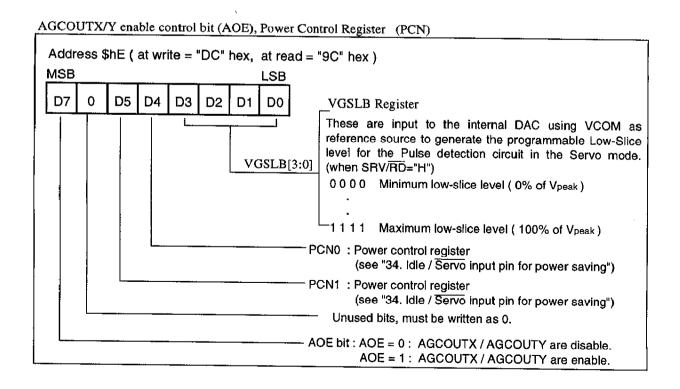


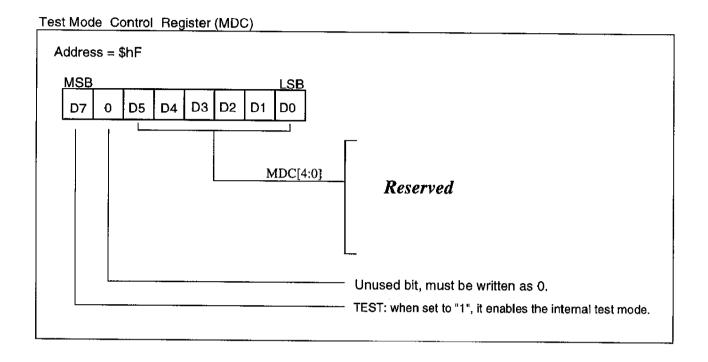




1-7WDOUT output type select bit (WDM), Write pre-compensation delay control register (WPE, WPN)

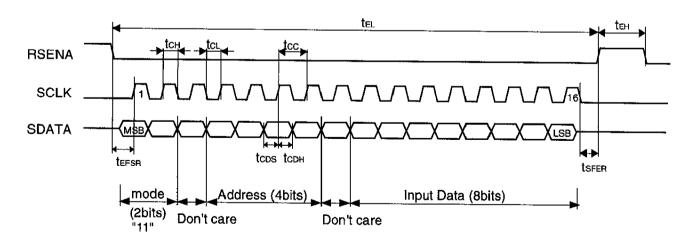






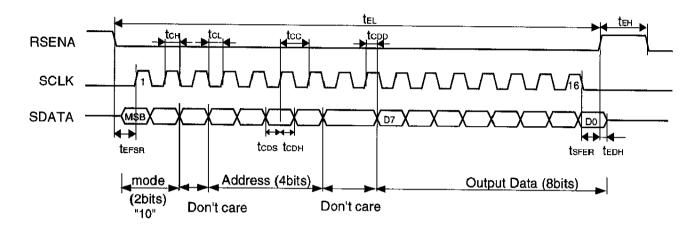
7. Read/Write timing of the control registers

< Write >



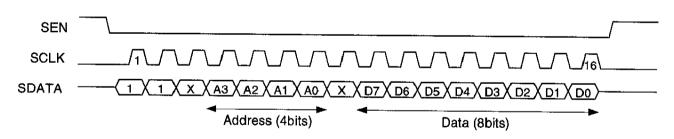
Read/Write timing of the control registers (cont)

< Read >

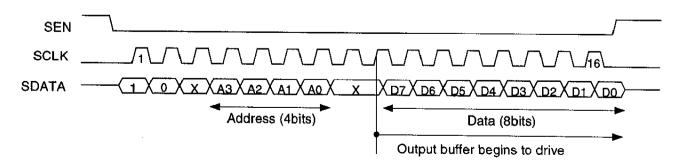


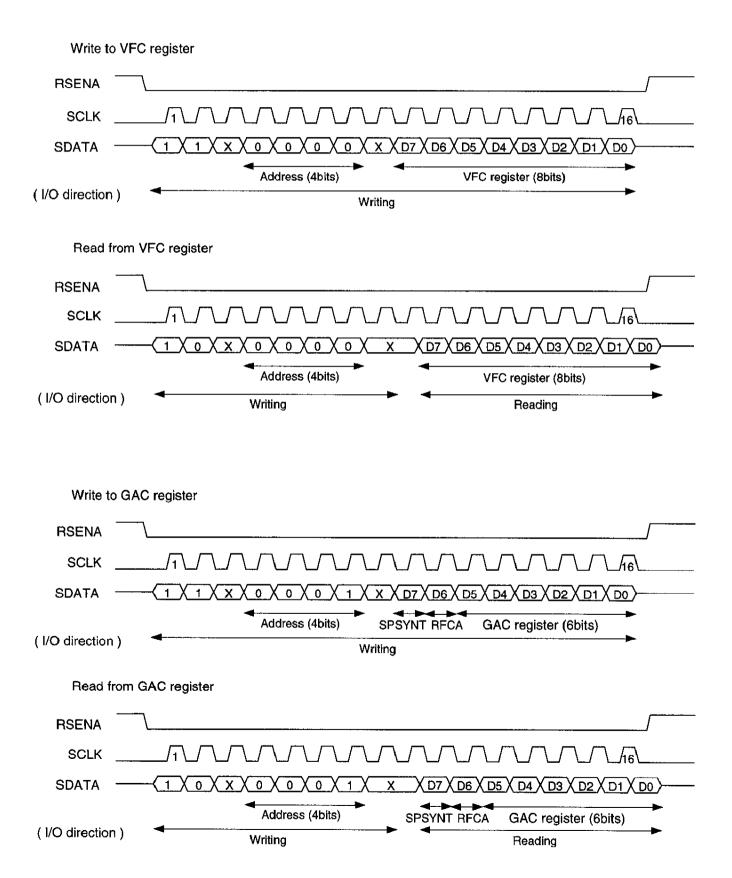
8. Write and read registers

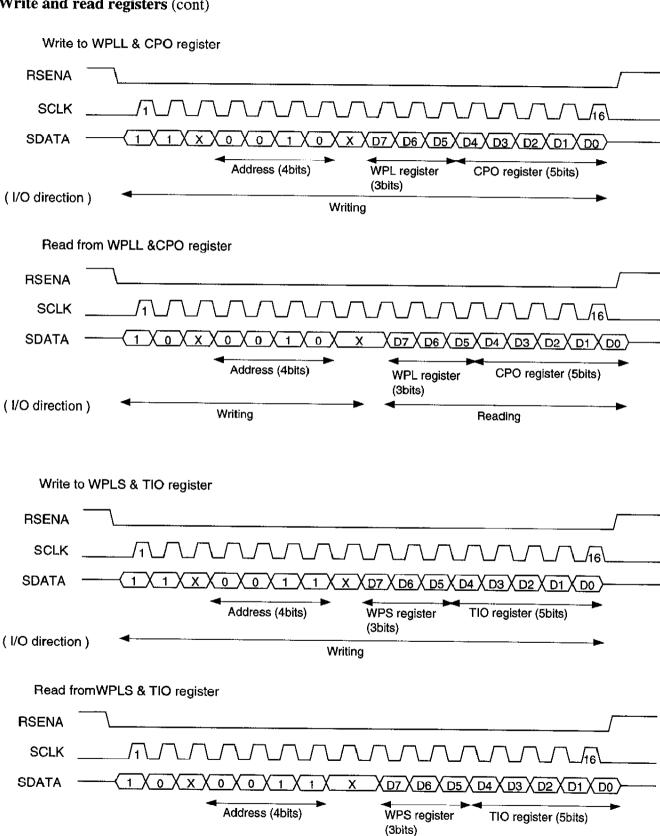
Write to register



Read from register





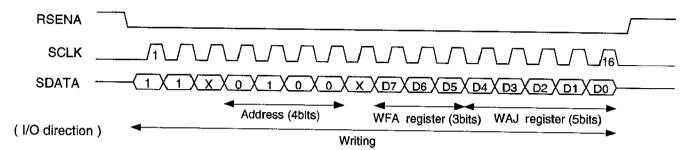


Reading

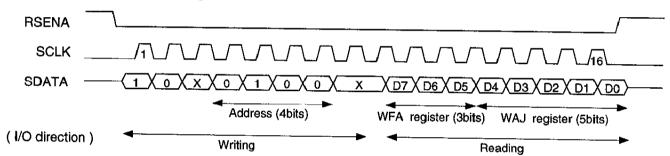
Writing

(I/O direction)

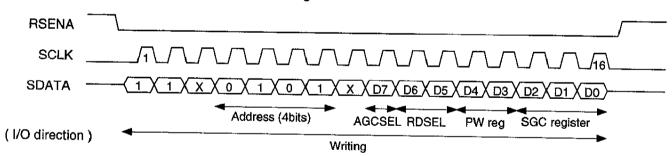
Write to WFA & WAJ register



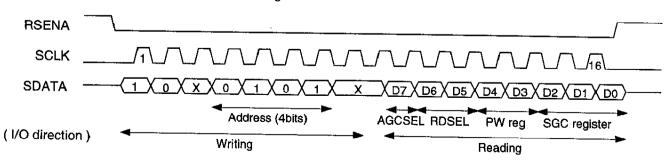
Read from WFA & WAJ register

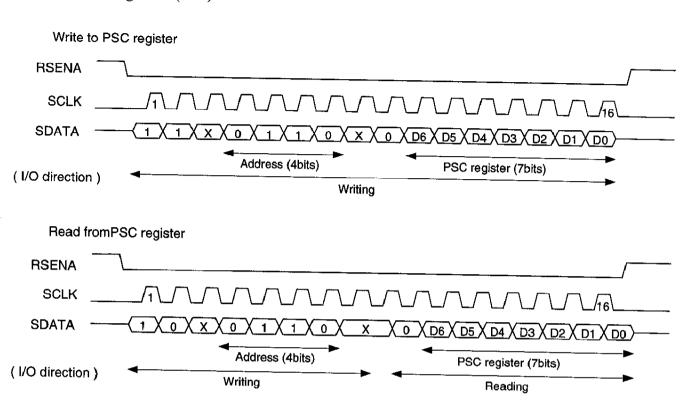


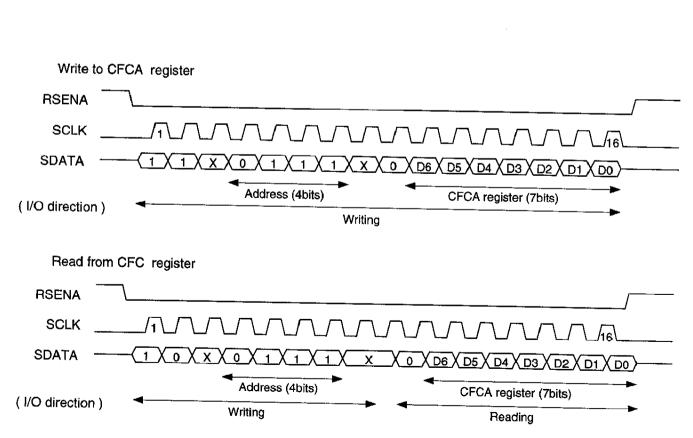
Write to AGCSEL bit, RDSEL, PW & SGC register



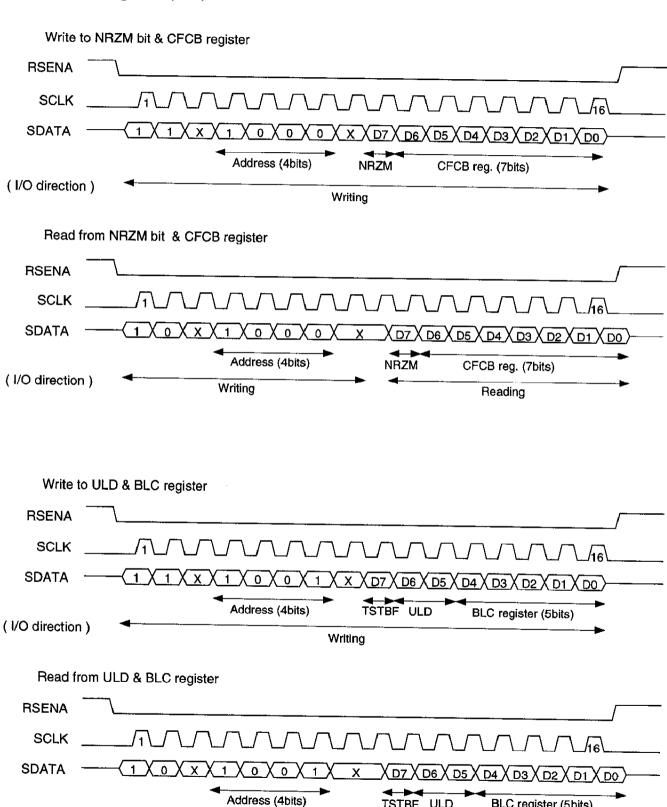
Read from AGS bit, RDS, PW & SGC register







(I/O direction)

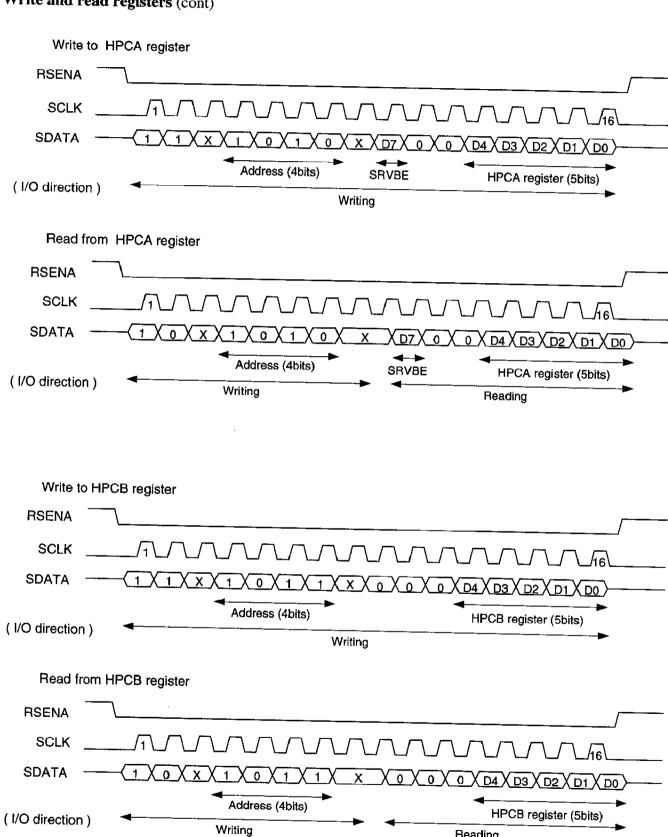


Writing

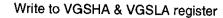
TSTBF ULD

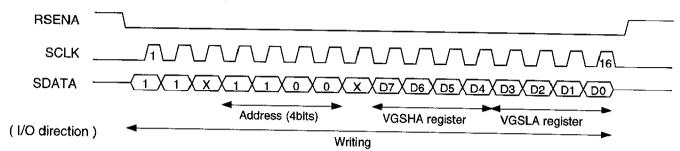
Reading

BLC register (5bits)

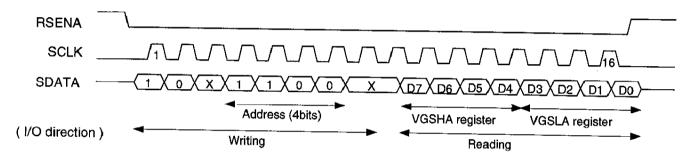


Reading

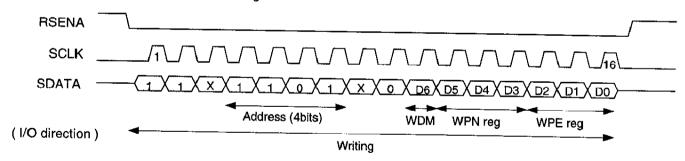




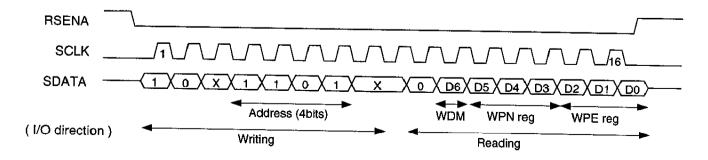
Read from VGSHA & VGSLA register

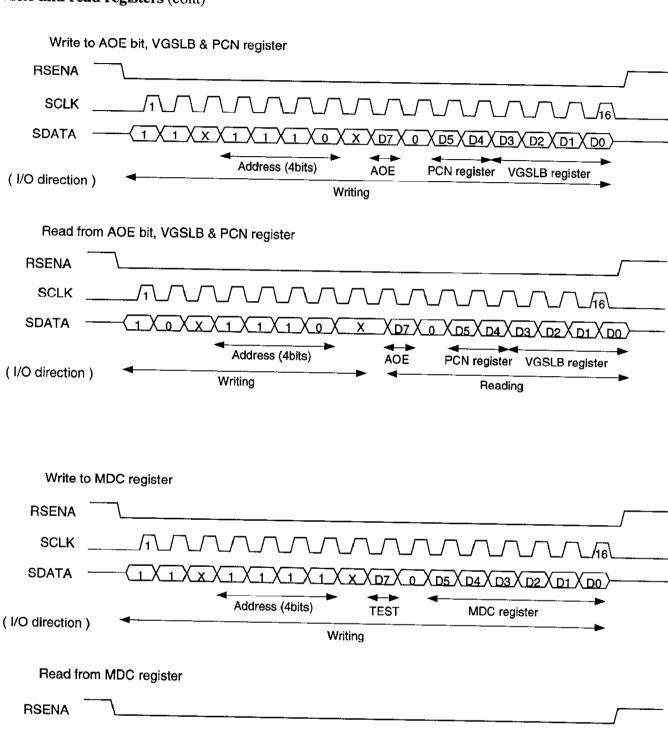


Write to WDM bit, WPN & WPE register



Read from WDM bit, WPN & WPE register





Address (4bits)

Writing

TEST

D4 X D3 X D2 >

MDC register

Reading

SCLK

SDATA

(I/O direction)

9. AGC(Automatic Gain Control) amplifier circuit

The AGC amplifier is a three-stage differential amplifier. The first stage has variable gain and the second and third stages have fixed gain. The AGC block consists of the first and second gain

stages. The output of the active filter (FILOUT and DIFOUT) stage is the third gain stage of the AGC block.

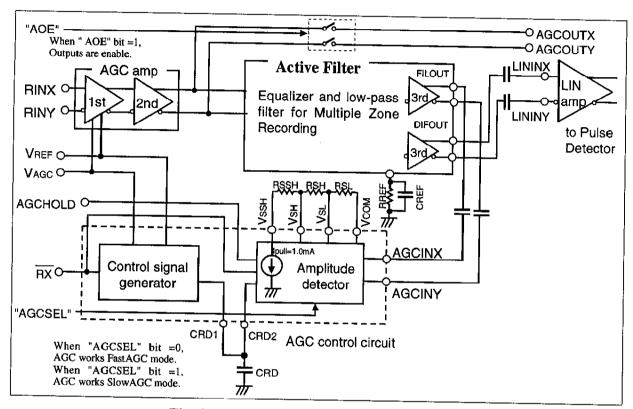


Fig. 9.1 Read Pulse Detector Block Diagram

The first-stage gain can be controlled in the range from - ∞ to approximately 17 dB by an amplitude control signal (VAGC) from the AGC control circuit. The first-stage gain is given by the following formula.

$$Av = K_1 \cdot \left(\frac{1}{1 + \exp\left(qVc/kT\right)} \right)$$

 $K_1 = 7.1$

 $V_C = V_{AGC} - V_{REF}$

q: unit electrical charge

k: Bolzmann constant

T: absolute temperature

The second-stage amplifier has fixed gains of

6dB. The third-stage amplifier within the Active filter has fixed gains of 20dB (at the outputs of FILOUT). The AGC full gain is 142V/V (= 43 dB).

When bit 7 of register address "1110" (AOE bit) is set to "1", AGCOUTX and AGCOUTY pins can be used to monitor the output of the AGC amplifier. These pins are open emitter type. When monitor them, please terminate to ground by $1K\sim1$ $0K\Omega$ resistor.

When bit 7 of register address "0101" (AGCSEL bit) is set to "0", AGC works FastAGC mode. When AGCSEL bit is set to "1", AGC works SlowAGC mode. The discharge current of AGC chargepump circuit is 200µA at FastAGC mode. It is 20µA at Slow AGCmode. The Charge current is 1mA at any mode.

The AGC amplifier gain control system is shown in figure 9.1. The AGC amplifier output is amplified by the post-amplifier and buffer amplifier, then passed through a low-pass filter. The low-pass filter output is connected to the differentiating amplifier, and is also feedback to the AGC control circuit. Here it is compared with reference voltages (V sH and VsL) that are set externally, then the external capacitor (C RD) is charged or discharged. The charging/discharging of the external capacitor varies the control signal VAGC which directly affects the gain of the AGC amplifier. The final amplitude VP (of the AGCINX and AGCINY waveforms) in this control system can be calculated from the following equations, assuming sine waveforms:

$$T_1 \times I \text{ ch} = T_2 \times I \text{ dis}$$
 (9.1)

$$T_1 = \left(1 - \frac{2}{\pi} \sin^{-1} \frac{V_{COM} - V_{SH}}{V_P}\right) \times T$$
 (9.2)

$$T_2 = \left(1 - \frac{2}{\pi} \sin^{-1} \frac{V_{COM} - V_{SL}}{V_P}\right) \times T$$
 (9.3)

From equations (9.1), (9.2), and (9.3):

$$\sin^{-1} \frac{V_{\text{COM}} - V_{\text{SH}}}{V_{\text{P}}} - \frac{I \, \text{dis}}{I \, \text{ch}} \sin^{-1} \frac{V_{\text{COM}} - V_{\text{SL}}}{V_{\text{P}}}$$
$$= \frac{\pi}{2} \left(1 - \frac{I \, \text{dis}}{I \, \text{ch}} \right) \qquad (9.4)$$

The final amplitude of the AGC amplifier loop is determined mainly by VSH bias level. If appropriate values are set for VSL, Ich and Idis, then from the preceding equations the final differential peak voltage V PDF is:

$$V_{PDF} = 4 (V_{COM} - V_{SH}) \times m \qquad (9.5)$$

where m = 1.02 to 1.04

$$V_{COM} = V_{CC} - 1.0V$$

The preceding V PDF is determined by the signal waveform, the output dynamic range of the amplifiers, and other factors. An appropriate value is VPDF = $1.7V \pm 0.1V$. Accordingly, (V com - VSH) should be around 0.41V. V SL should normally be about:

$$V_{COM} - V_{SL} = 0.67 (V_{COM} - V_{SH})$$
 (9.6)

The value must be determined from the resolution

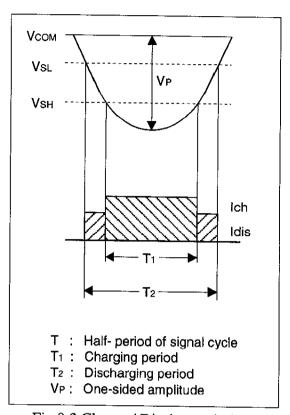


Fig 9.2 Charge / Discharge timing

specifications, however. The procedure is to determine VsH and VP from equation (9.4), then set Ich = 1.0mA and Idis = 0.2mA to determine VSL. Attenuation of signal amplitudes internal to the disk drive with respect to signal amplitudes external to the disk drive must be considered. For example, from equation (9.5), (V COM - V SH) =0.41V and m = 1.03 gives $V_{PDF} = 1.69 V$, and from equation (9.4), $(V_{COM} - V_{SL}) = 0.10 \text{ V}$, but if the input amplitude is instantaneously attenuated from its previous value to a new value that is not larger than (VCOM - VSL), the amplitude recovery time might be excessively long. Next, it is necessary to consider the relationship of the recovery time to the charge-discharge capacitor CRD. The CRD capacitance should be close to the following value:

$$C_{RD} = \frac{300000}{T_{ransfer rate (Mhps)}} (pF) (9.7)$$

10. Setting for Vsl., Vsh, Vssh level

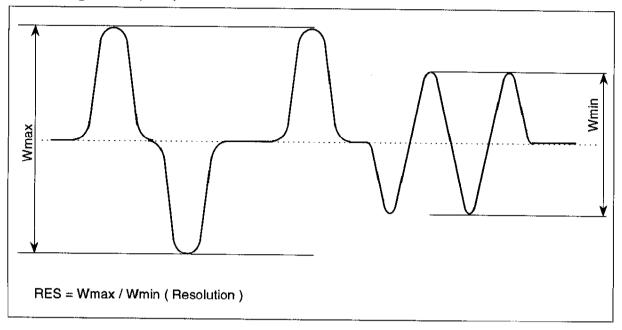


Fig. 10.1 Example of input signal for HD153035F

(1) VsH level:

VFILOUT = Peak to peak output signal amplitude of between FILOUTX and FILOUTY

$$(VCOM - VSH) = VFILOUT + m + 4,$$

Where VFILOUT=2.0V, m=1.03

 $V_{COM} - V_{SH} = 0.413 V$

Where internal pull down current lpull = 1.0mA Hence, RSH + RSL = 413 Ω

(2) Vs. level:

$$(V_{COM} - V_{SL}) = (V_{COM} - V_{SH}) + RES + 1.1$$

Where RES=1.6,

 $V_{COM} - V_{SL} = 0.235 V$

Therefore, RSL = 235 Ω , RSH= 178 Ω

(3) Vssh level:

$$(V_{COM} - V_{SSH}) = (V_{COM} - V_{SH}) \times RES \times 1.1$$

 $V_{COM} - V_{SSH} = 0.727 V$

Hence, RSSH + RSH + RSSL = 727 Ω

RSSH = 314 Ω

$$\therefore RSL = 240 \Omega$$

$$RSH = 180 \Omega$$

RSSH = 300 Ω

11. Programable Active Filter

Active Filter consists of equalizer and electronic filter. Electronic filter is 7-pole, Bessel-type, low-pass filter and can be used in multiple zone recording (MZR) design. Cut-off frequency of filter is set by writing to register CFC. Writing to the

HPC register will set the high-pass cut-off frequency of the differential amplifier. The equalizer is double differentiation pulse sliming equalization. The Boost level is set by writing to register BLC.

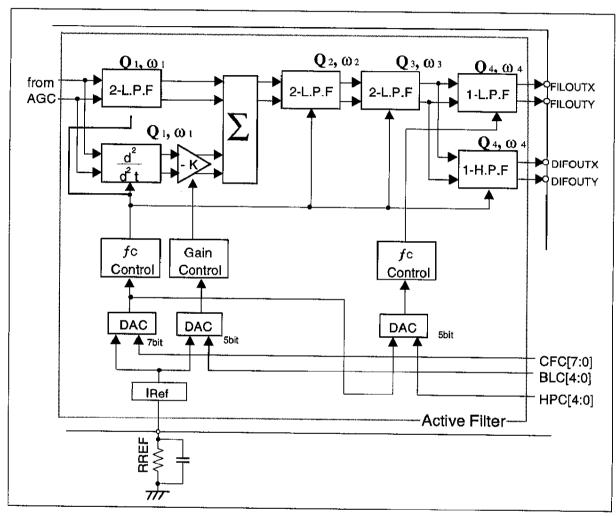
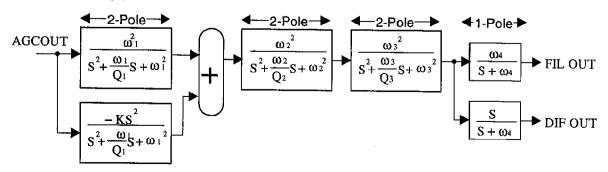


Fig. 11.1 Active Filter Block Diagram

Transfer function



Normalized (Constant of 7-	pole Bessel filter
--------------	----------------	--------------------

Parameter	Normalized constant (ωc = 1)
ω ₁ ²	2.94930
<u>ω</u> 1 / Q1	3.22597
ω ₂ ²	3.32507
<u></u>	2.75939
w³	4.20534
ω ₃ / Q ₃	1.82031
<u></u>	1.68536

11.1 CFC and HFC register application

CFC register controls low pass cutoff frequency of the Active filter for FILOUTX/Y. HFC register controls high pass cutoff frequency of the Active filter for DIFOUTX/Y. When SRV/RD pin is low, the cutoff frequency is decided by CFCA and HPCA register values. When SRV/RD pin is high, the

cutoff frequency is decided by CFCB and HPCB register value. When HPC register value is "0 0000", DIFOUTX/Y output is shifted 90° (defferential outputs) from FILOUTX/Y. Normally, HPC register is set "0 0000".

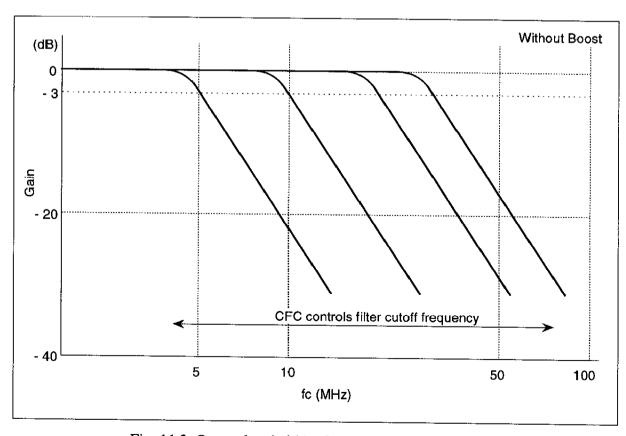


Fig. 11.2 Output bandwidth of FILOUTX and FILOUTY

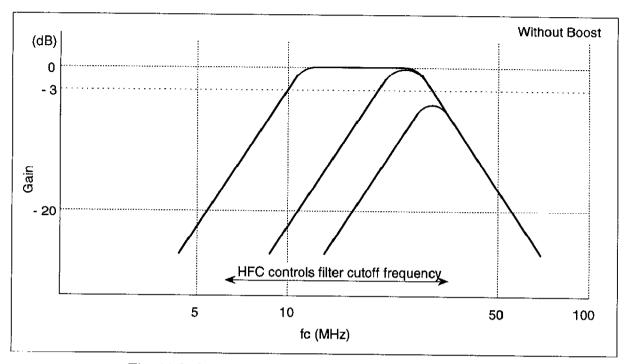


Fig. 11.3 Output bandwidth of DIFOUTX and DIFOUTY

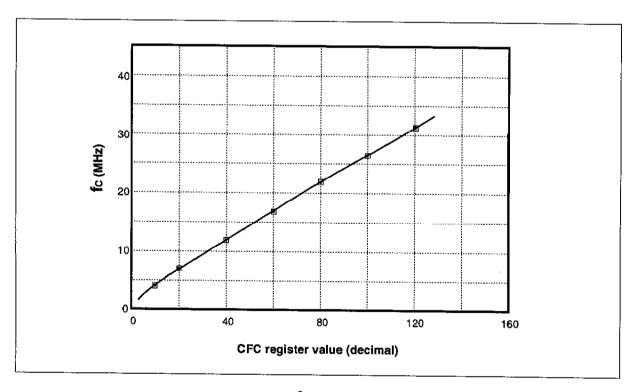


Fig 11. 4 fc vs CFC register

11.2 BLC register application

BLC register controls the Active filter Boost level. When sets BLC value except "0", filter boost is active, gets slimming pulse wave and low pass filter's cutoff frequecy will be shifted to higher

frequency.

High boost level can get slimmed pulse easily, but it is caused distortion and noise. Boost level should be optimized for each zone.

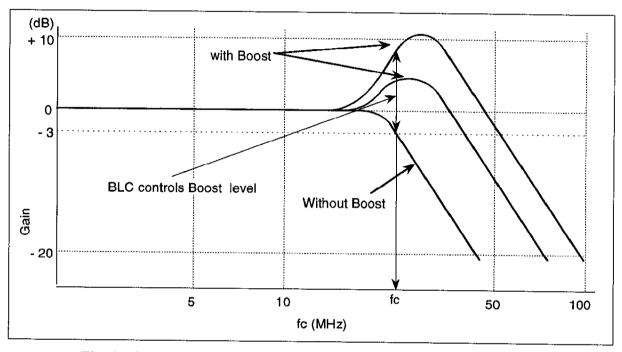


Fig. 11.5 Output bandwidth of FILOUTX and FILOUTY (with Boost)

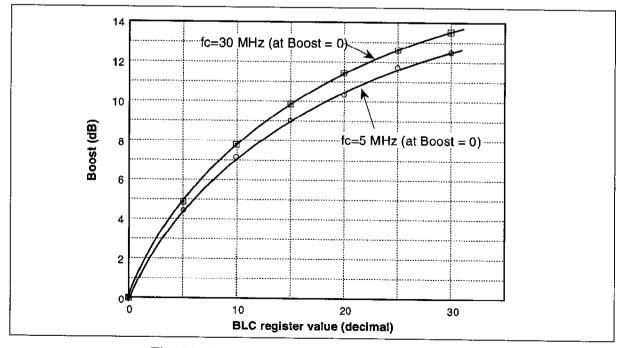


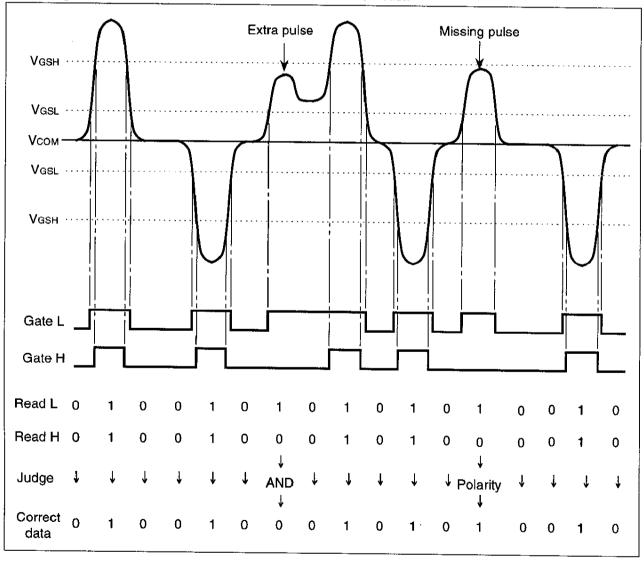
Fig. 11. 6 Boost vs BLC register at fc=30MHz

12. Gate Generator Circuit

A gate signal is used to gate the read signal near its peak value to remove incorrect read pulse. This gating signal is created by the gate generator circuit. The principle is to ensure that the read pulse crosses two programmable slice levels before being gated out as PDRD signal. For normal read mode, shifter and logic are used to qualify pulses that crosses only the low slice level or multiple peaks that would require polarity checking. The two slice levels

VGSL and VGSH are set by writing to the VGSH and VGSL. 4-bit registers. The High slice level is programmed to covered 0% to 100% of the VSH level and the Low slice level would covered 0% to 100% of the VSH. In servo mode, if one pulse is missing because it is not meeting the Low slice level, the next qualifying pulse will be dis-qualified as well.

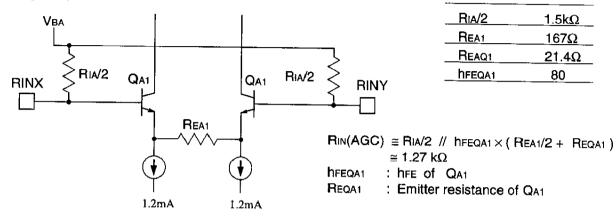




13. Input/Output impedance of the Read Pulse Detector's amplifiers

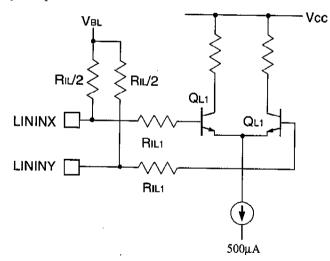
■ AGC amplifier

Input impedance



■ LIN amplifier

Input impedance



RıL/2	4.5kΩ
R _{IL1}	100Ω
REQL1	103Ω
hFEQL1	80

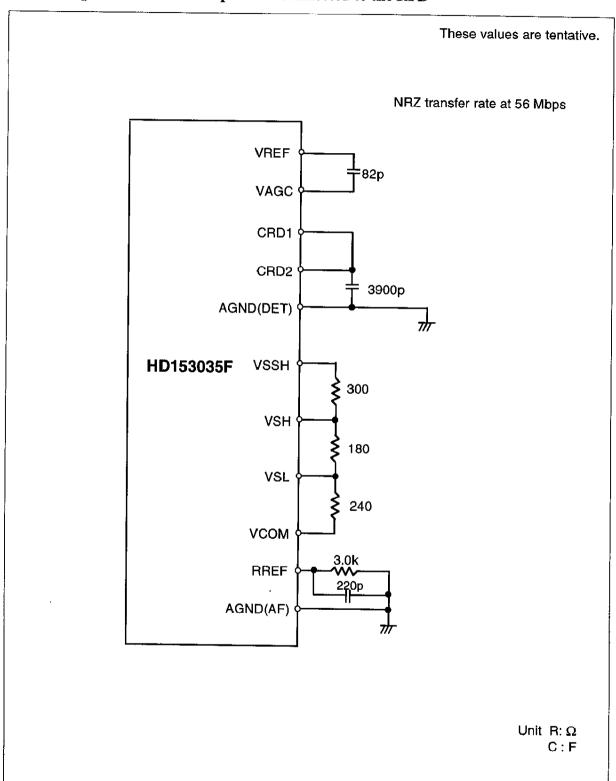
 $Rin(LIN) \cong RiL/2 // (RiL1 + hFEQL1 \times REQL1)$

≅ 2.92kΩ

hFEQL1 : hFE of QL1

REQL1 : Emitter resistance of QL1

14. Example of External Components Connected to the RPD



15. P/H circuit for Servo

The P/H circuits consists of a full-wave rectifier, sample and hold, followed by a gain stage that drives external capacitors through switches. Four outputs are made available to enable detection for four channel servo. When, the DUMP signal goes low, all output capacitors are discharged. Then, the CHA signal is activated producing a succession of four negative pulses. During each negative going

pulse, one of the four external capacitors is shorted to the output of the gain stage for holding the peak of the servo burst signal into the capacitor.

Hitachi use OUT0 and OUT1 pin to monitor the internal signals in test mode. So, if you don't use P/H circuit, the P/H Vcc pin(#10) should be connected to the power supply line.

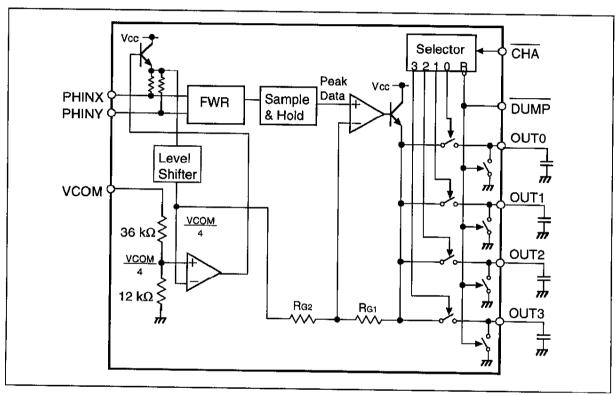
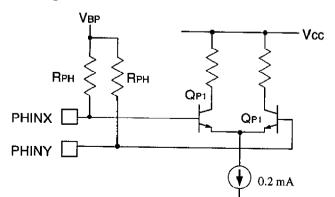


Fig. 15.1 P/H circuit Block Diagram

■ Input impedance of P/H circuit



<u> Рең</u>	6 kΩ
REQP1	258 Ω
hFEQL1	80

 $Rin(LIN) \cong RPH // (hfeql1 \times ReqP1)$

≅ 4.87 kΩ

hfeqp1 : hfe of Qp1

REQP1 : Emitter resistance of QP1

16. Servo application example

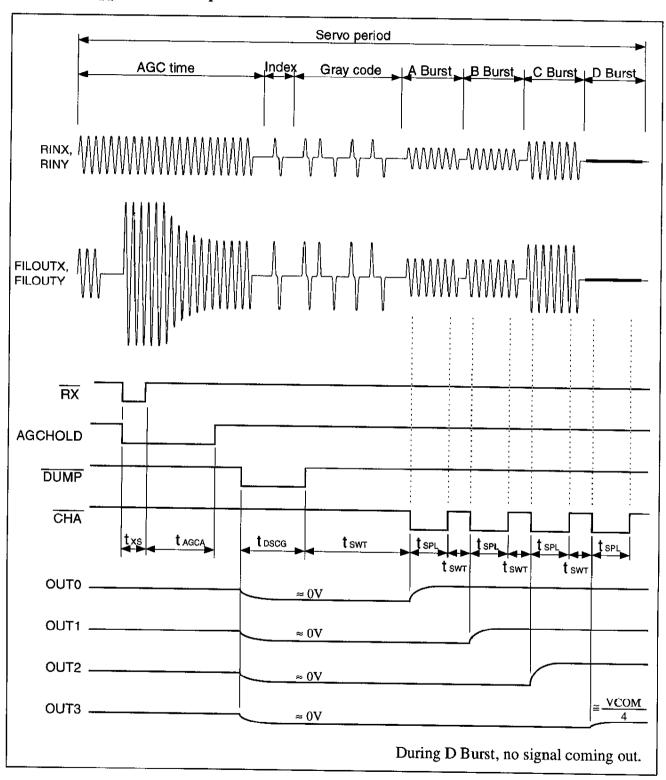
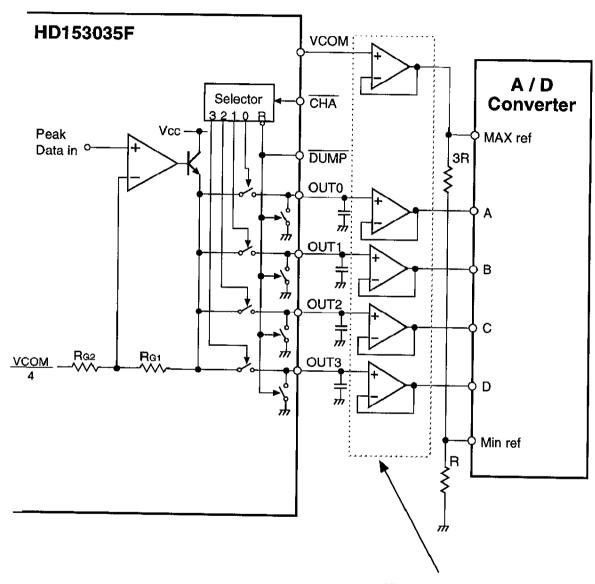


Fig. 16.1 Timing Diagram of the servo function

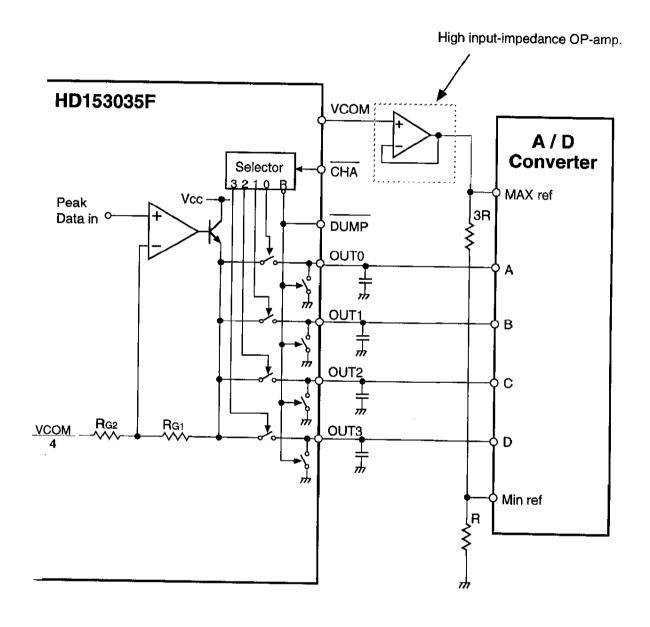
17. Servo application example (external components)

(1) Low input impedance Digital to Analog Converter application

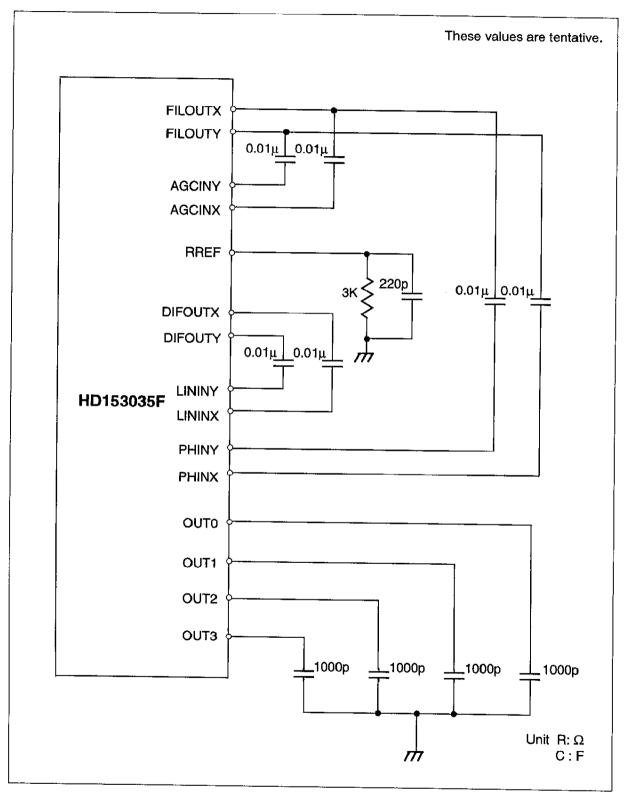


High input-impedance OP-amp.

(2) High input impedance Digital to Analog Converter application

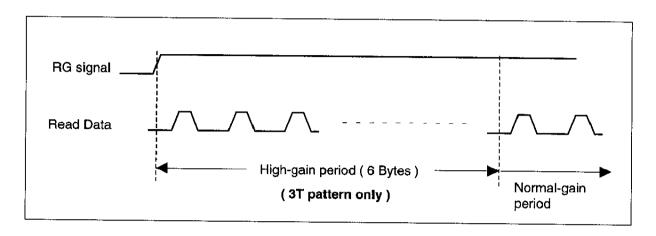


17. Example of External Components Connected to the RPD

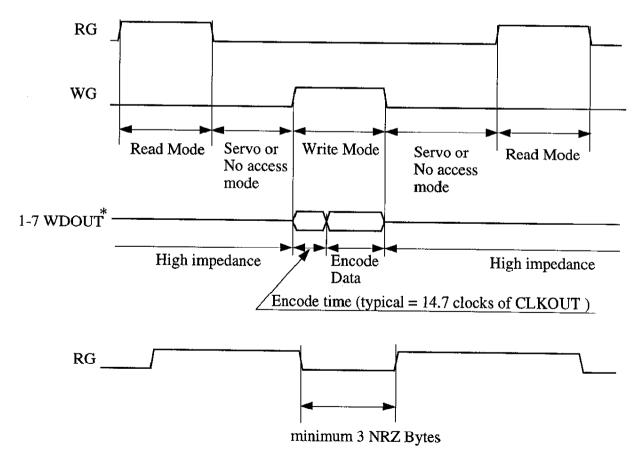


18. Sync Field Detection

The high-gain period can be set to last six NRZ bytes after the RG signal is goes active.



Read and write mode



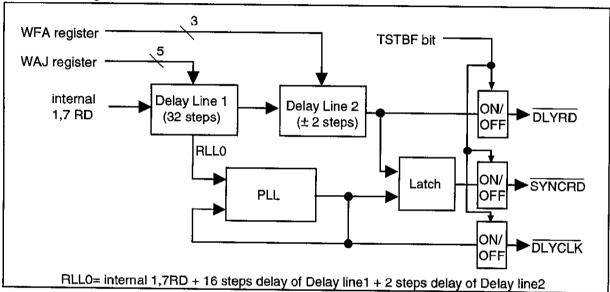
*) 1-7 WDOUT is synchronized with the rising edge of CLKOUT

19. Window Adjustment Circuit

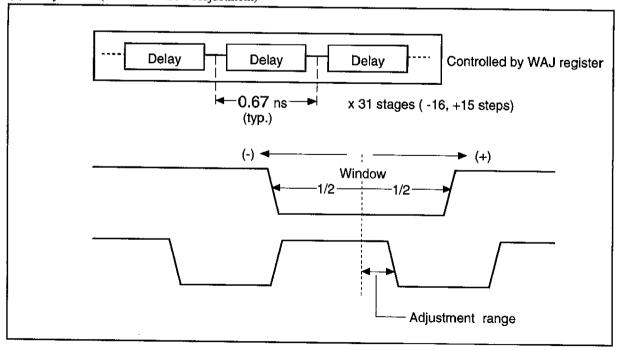
The HD153035F has two on-chip delay lines for centering the decode window. First delay line has 32 taps for coarse adjustment that can be selected by register WAJ. Second delay line has 5 taps for fine adjustment that can be selected by register WFA.

Window centering adjustment can be performed automatically by a microcontroller. This adjustment function can also be used for preshipment window margin test.

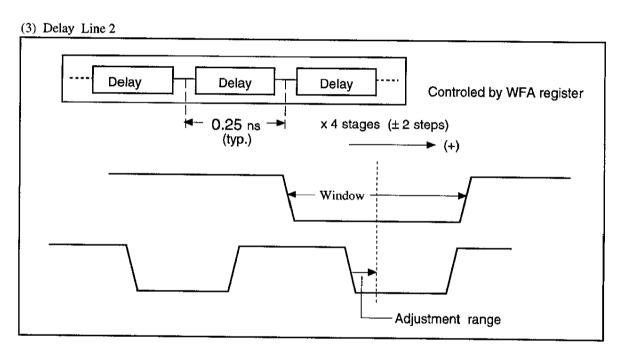




(2) Delay Line 1 (Coarse Window Adjustment)



WAJ Reg	gister			LSB	
4	3	2	1	0	Delay line 1 tap No.
0	0	0	0	0	- 16 (- 10.72 ns typ.)
	•				•
0	1	1	11	0	- 2 (- 1.34 ns typ.)
0	1	1	1	1	- 1 (- 0.67 ns typ.)
1	0	0	0	0	0
1	0	0	0	1	+ 1 (+ 0.67 ns typ.)
1	0	0	1	0	+ 2 (+ 1.34 ns typ.)
	•				:
1	1	1	1	1	+ 15 (+ 10.05 ns typ.)



WFA Reg	jister	LSB	
7	6	5	Delay line 2 tap No.
0	1	0	– 2 (- 0.50 ns typ.)
0	0	1	- 1 (- 0.25 ns typ.)
0	0	0	0
_1	0	1	+ 1 (+ 0.25 ns typ.)
_1	1	0	+ 2 (+ 0.50 ns typ.)

20. Decode Clock Generator's VFO

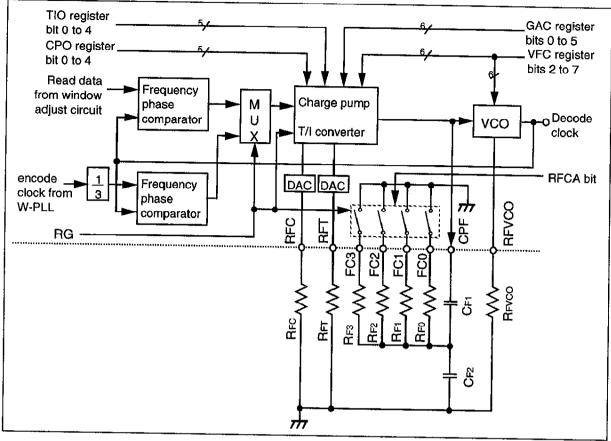


Fig. 20.1 R-PLL Block Diagram

Function

- The phase of the VCO clock is synchronized to the read data from the window adjust circuit.
- The frequency-phase comparator operates in the frquency-phase comparison mode while acquiring phase lock during the sync field, and in phase comparison mode during synchronization in the data field.
- The charge pump and T/I converter circuits both operate while the phase lock is being acquired.
 During synchronization, only the T/I converter operates.
- The VFO is synchronized with the encode clock until the read gate signal (RG) is asserted.
- The VCO center frequency can be programmed

- by rewriting bits 0 to 7 of the VFC register, so multiple zone recording can be implemented with a single external resistor.
- The charge pump can select eight levels currents, the reference value of which is controlled by external resistor RFC. Bit 3 to 5 in register GAC selects these eight levels.
- The T/I converter provides one of eight output currents as selected by bits 0 to 2 of the GAC register.
- The loop filter attenuation ζ can be selected by bit 6 (RFCA bit) of register GAC (two selections). Independent settings can be made for high gain and normal gain.

Frequency Encode Charge vco 127 phase clock pump comparator bit 2 to 7 bit 0 to 7 **PSC** register VFC register bit 0 to 6 bit 0 to 7 1 2 to 255 SPSYNT bit at fmax / flow ≤ 4 fLOW = minimum transfer rate x 1.5foscolk = $\frac{M}{64}$ x flow (M = 2 t o 127) fvco(w) = $\frac{N1}{64}$ x flow (N1 = 64 to 255)

21. Encode Clock Generator's Frequency Synthesizer

Fig. 21.1 W-PLL Block Diagram

Function

- A PLL-type frequency synthesizer generates the encode clock.
- The encode clock frequency can be set by bits 0 to 7 of register VFC to a value of N/64 times the minimum data transfer rate (innermost track on the disk), where 64≤ N≤ 255.
- The lock/unlock monitor function (ULD line) can prevent data from being written when a drive fault occurs.
- The VCO center frequency can be selected by bits 0 to 7 of register VFC, so a single external resistor RSC covers the entire setting range.
- The operating mode can be selected by bit 7 (SPYNT bit) of GACregister. When use over 50 Mbps, this bit has to be set low.

Operation

- Input a reference clock to OSCCLK at (1.5 xM)/6
 4 times the driver's minimum transfer rate.
- This signal input to the frequency-phase
- comparator at 1/M.
 - The VCO clock is divided by 1/64 to 1/255,
- depending on bits 0 to 7 of VFC register, and input to the frequency-phase comparator.

 $2 \le M \le 127$, $64 \le N1 \le 255$.

fvco(w) : VCO output frequency

flow: Encoder clock frequency corresponding to the minimum

transfer rate.

22. Calculation of PLL Constants

- I. Decode Clock Generator's VFO (R-PLL)
 - 1. VCO center frequency for

2. VCO gain Kor

Kor =
$$(1.536 \times 10^9) \cdot \sqrt{\frac{N}{\text{RFVCO}}} \left(\frac{\text{rad}}{\text{sec} \cdot \text{V}}\right)$$
 (1.2)

3. Charge pump current I CR

$$I_{CR} = \frac{2.5 \times 10^4}{R_{FC}} \cdot \frac{P}{8}$$
 (mA)(1.3)

where $1 \le P \le 8$

4. T/I converter current ITR

ITR =
$$(3.52 \times 10^{3}) \cdot \frac{N \cdot L}{500 + R_{FT}}$$
 (µA)····· (1.4)

where $0 \le L \le 7$

5. Characteristic frequency (high gain) ω_{nRH}

$$\omega_{\text{nRH}} = \sqrt{\frac{\text{Kor} \cdot \left(\frac{\text{ICR}}{6} + \text{ITR}\right)}{\pi \cdot \text{CF1}}} \qquad \left(\frac{\text{rad}}{\text{sec}}\right).$$
(1.5)

Characteristic frequency (normal gain) ω nRN

$$\omega_{nRN} = \sqrt{\frac{\text{Kor} \cdot \text{ITR}}{\pi \cdot \text{CF1}}} \quad \left(\frac{\text{rad}}{\text{sec}}\right) \quad (1.6)$$

7. Attenuation (high gain) ζ_{RH}

$$\zeta_{RH} = \frac{\left(C_{F1} + C_{F2}\right)}{2} \cdot \frac{1}{\frac{1}{R_{FB}} + \frac{1}{R_{FB}}} \cdot \omega_{nRH} \qquad (1.7)$$

where RFA and RFB = RF0 and RF1 when GAC register bit 6 = 0 RF2 and RF3 when GAC register bit 6 = 1 8. Attenuation (normal gain) ζ_{RN}

$$\zeta_{RN} = \frac{(C_{F1} + C_{F2})}{2} \cdot R_{FA} \cdot \omega_{nRN} \qquad (1.8)$$

where RFA = RF0 when GAC register bit 6 = 0
RF2 when GAC register bit 6 = 1

II. Encode Clock Generator's Frequency Synthesizer (W-PLL)

1. VCO center frequency flow

2. VCO gain Kow

Kow =
$$(1.056 \times 10^9) \cdot \sqrt{\frac{N}{\text{Rsvco}}} \left(\frac{\text{rad}}{\text{sec} \cdot \text{V}}\right)$$
(II.2)

3. Charge pump current ratio No

$$Nc = \inf [16 \cdot \sqrt{\frac{N1}{N1_{MAX}}} - 8]$$
 (II.3)

When N1=N1 MAX, set the Nc=7

Note1: int[] is the integer value calculated by discarding the fractional part of the value.

4. Charge pump current 1cw

$$I cw = \frac{5.3}{Rsc} \cdot \left(1 + \frac{Nc}{8}\right) \qquad (A) \qquad (II.4)$$

Characteristic frequency ω nw

$$\omega_{\text{ nW}} = \sqrt{\frac{\text{Kow} \cdot \text{Icw}}{2\pi \cdot \text{N1} \cdot \text{Cs1}}} \left(\frac{\text{rad}}{\text{sec}}\right) \tag{II.5}$$

6. Attenuation ζw

$$\zeta_{W} = \frac{(Cs_1 + Cs_2)}{2} \cdot Rs_1 \cdot \omega_{nW} \qquad (II.6)$$

Table 22. 1 VCO Oscillation Frequency and Transfer Speed for Settings of Register VFC (at fMAX/fLOW = 3.98)

							/
	VFC register					Example:	
	MSB LSB		Transfer	Transfer	1-7 clock	RFVC0= $2.55 \text{ k}\Omega$,	Rsvco = $5.24 \text{ k}\Omega$
N1	76543210	N	speed (Mbps)	speed ratio	frequency (MHz)	R-VCO setting frequency (MHz)	W-VCO setting frequency (MHz)
0							()
•	_ Inhibit						
	_						
63	70.						
64	01000000	16	14.00	1.000	21.00	21.18	21.30
65	01000001	16	14.22	1.016	21.33	21.18	21.30
66	0 1 0 0 0 0 1 0	16	14.44	1.031	21.66	21.18	21.30
67	01000011	16	14.66	1.047	21.98	21.18	21.30
68	01000100	17	14.88	1.063	22.31	22.50	22.63
•	•	•	•	•	•	•	•
•	•	•	•	•	•	•	•
•	•	•	•	•	•	•	
	•	•	•	•	•	•	•
-	•	•	•	•	•	•	
127	0 1 1 1 1 1 1 1	31	27.78	1.984	41.67	41.03	41.26
128	10000000	32	28.00	2.000	42.00	42.35	42.60
129	10000001	32	28.22	2.016	42.33	42.35	42.60
130	10000010	32	28.44	2.031	42.66	42.35	42.60
	•	•	•	•	•	•	•
-	•	•	•	•	•	•	•
<u> </u>	•	•	•	•	•	•	•
•	•	•	•	•	•	•	•
•	•	•	•	•	•	•	•
	•	•	•	•	•	•	•
•	•	•	•	•	•	•	•
253	11111101	63	55.34	3.95	83.02	83.38	83.86
254	1 1 1 1 1 1 0	63	55.56	3.97	83.34	83.38	83.86
255	11111111	63	55.78	3.98	83.67	83.38	83.86

Table 22. 2 Charge pump Output Current Settings with GAC Register

		GA	.C reg	ister			Example: $R_{FC} = 5.1 k\Omega$
	Bits	5	4	3	Р	Charge pump output current ratio	Charge pump output current (mA)
		0	0	0	1	1	0.613
2		0	0	1	2	2	1.226
3		0	1	0	3	3	1.838
4		0	1	1	4	4	2.451
5	,	1	0	0	5	5	3.064
6		1	0	1	6	6	3.677
7		1	1	0	7	7	4.289
8		1	1	1	8	8	4.902

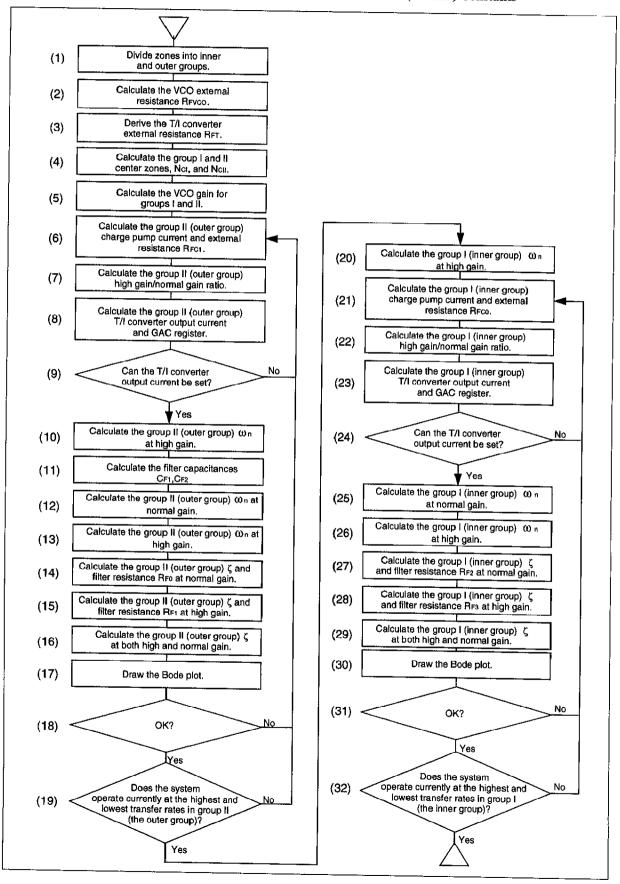
$$I_{CR} = \frac{2.5 \times 10^4}{R_{FC}} \cdot \frac{P}{8} \qquad (mA)$$

Table 22. 3 T/I Output Current Settings with GAC Register

	GA	C reg	ister		T/I output	Example: $R_{FT} = 11k\Omega$ N=63
	Bits 2	1	0	L	T/l output current ratio	T/I output current (μA)
1_	0	0	0	0	0	0.0
2	0	0	1	1	1	19.3
3	0	1	0	2	2	38.6
4	0	1	1	3	3	57.9
5	1	0	0	4	4	77.1
6	1	0	1	5	5	96.4
7	1	1	0	6	6	115.7
8	1	1	1	7	7	135.0

$$I_{TR} = (3.52 \times 10^{3}) \cdot \frac{N \cdot L}{500 + R_{FT}}$$
 (µA)

23. Flowchart of Procedure for Setting Decode Clock Generator VFO (R-PLL) Constants



24. Flowchart Explanation (R-PLL)

(1) Divide zones into groups

Divide the zones selected in synthesizer step (1) into two groups (I and II) having equal frequency ranges. Divide the groups at the following transfer rate TRgr:

(2) VCO external resistance R FVCO

Use equation (1.1) to calulate the external resistance RFvco that makes the VCO oscillate at 1.5 times the minimum transfer rate (N=16)

(3) T/I converter external resistance R FT

Find the RFT values at the minimum transfer rate as shown in Fig. 24.2.(RFT vs Data transfer rate).

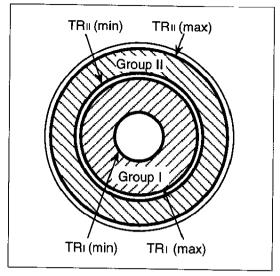


Fig. 24.1. Divide zone image

(4) Center zones TR ci and TRcii of group I and II

Calculate the midpoint (TR ci & TRcii) between the minimum transfer rate (TRmin) and maximum transfer rate (TRmax) at each groups (caluculate at step (1)), and from the zones selected in step (1), find the value of N (N ci & Ncii) that comes closest toTR ci & TRcii.

$$TRc_{I} = \frac{TR_{I} (min) + TR_{I} (max)}{2}, \quad TRc_{II} = \frac{TR_{II} (min) + TR_{II} (max)}{2}$$

(5) VCO gain Kon in groups I and II

Use equation (I.2) to calculate the VCO gain K on at the center zones (N=N ci and N=N cii) in groups I and II.

(6) Charge pump current I ca in group II

Select the charge pump current level within the following range:

$$Icr \le 5.0$$
 (mA)

Calculate the values for the external resistances R FC and P from equation (I.3). So that the current has the desired value. See Table 22.2 for the relationship between the value of P and GAC register.

(7) High gain/normal gain ratio in group II.

Set the current ratio gg between high and normal gain. This value is depend on HDA system. Normally,

(8) Group II T/I conversion output current I

Determine the value of $L(0 \le L \le 7)$ using equation (I.4), so that the following equation is satisfied:

$$ITR = \frac{ICR}{6(g_G - 1)}$$

See Table 22.3 for the relationship between the value of L and GAC register.

(9) Analysis

Determine if the T/I converter output current can be set.

(10) Group II High Gain ωn

After determining the group II center zone N cii phase pull-in time Taq taking into consideration the high gain set time, and determine the high gain characteristic frequency ω_{nRH} using the following equation.

$$\omega$$
 nRH • Tag = 2.5

(Adjust so that this value is in between 2 to 4.)

(11) Filter Capacitances C F1 and CF2

Calculate the filter capacitance C $_{\text{F1}}$ by substituting the high gain characteristic frequency ω_{nRH} calculated in item (10) above in formula I.5.

Also, set the ratio between C $_{\text{F1}}$ and C $_{\text{F2}}$ taking into consideration high region jitter suppression and phase margin. We recommend deriving C $_{\text{F2}}$ using the following equation.

$$CF2 = \frac{1}{45} \cdot CF1$$

(Adjust so that this value is in between 1/20 to 1/100.)

(12) Group II Normal Gain ωn

Compute the normal gain characteristic frequency ω_{nRN} by substituting the derived value of C F1 into formula I.6.

(13) Group II High Gain ωn

Compute the high gain characteristic frequency ω_{nRH} by substituting the derived value of C F1 into formula 1.5.

(14) Group II Normal Gain ζ RN and Filter Resistance R F0

Set the normal gain attenuation ratio $\zeta_{\rm RN}$ with stability as the main criteria.

The equation below indicate the recommend value . $\zeta_{RN} \cong 1.0$

Calculate the filter resistance R F0 by substituting that value into formula I.8

(15) Group II High Gain CRH and Filter Resistance RF1

Set the normal gain attenuation ratio $\zeta_{\rm RH}$ with stability as the main criteria.

The equation below indicate the recommend value . $\zeta_{RH} \cong 0.8$

Calculate the filter resistance R F1 by substituting that value into formula 1.7.

(16) Group II High Gain CRH and Normal Gain CRN

Calculate the attenuation ratios ζ_{RH} and ζ_{RN} by substituting the values of R F0 and RF1 into equations I.7 and I.8.

(17) Bode Plot Construction

Compute the open loop transfer function G(s) and construct the Bode plot.

(18) Analysis

Determine if the system is suitable from the open and closed loop characteristics.

(19) Analysis at TRmin and TRmax

Repeat the analysis of item (17) and (18) for group II TRmin and TRmax.

(20) Group I High Gain ωn

After determining the group I center zone N α phase pull-in time Taq, taking into consideration the high gain set time, and determine the high gain chracteristic frequency α RH using the following equation α RH • Taq = 2.9

(Adjust so that this value is in between 2 to 4.)

(21) Group I Charge Pump Current I CR

Calculate the charge pump current I cR by substituting the high gain characteristic frequency computed in item (20) above into formula I.5.

Here, set the charge pump current level within the following range:

ICR ≤ 5.0mA

Now, derive a value for P using equation 1.3 so that the desired charge pump current is achieved. See Table 22.2 for the relationship between the value P and GAC register.

(22) Group I High gain / Normal Gain Ratio

Set the high gain to normal gain current ratio ga.

 $g_{G} = 16$ (Adjust so that this value is in between 11 to 21.)

(23) Group I T/I Converter Output Current I TR

Determine a value of L (0 \leq L \leq 7) using equation (I.4) so that the following equation

$$ITR = \frac{ICR}{6(QG-1)}$$

See Table 22.3 for the relationship between the value L and GAC register.

(24) Analysis

Determine if the T/I converter output current should be set .

(25) Group I Normal Gain ωn

Calculate the normal gain characteristic frequeny ω_{nRN} by substituting the LTR derived above into formula I.6.

(26) Group I High Gain ωn

Calculate the high gain characteristic frequeny ω_{nRH} by substituting the Icr derived above into formula I.5.

(27) Group I Normal Gain ζ RN and Filter Resistance R F2

Set the normal gain attenuation ration ζ_{RN} with stability as the main criteria. The equation below indicate the recommend value.

CRN ≅ 1.0

Calculate the filter resistance R F2 by substituting that value into formula 1.8.

(28) Group I High Gain ζημ and Filter Resistance R F3

Set the high gain attenuation ration ζ_{RH} with stability as the main criteria.

The equation below indicate the recommended value.

ζян ≅ 0.8

Calculate the filter resistance R F3 by substituting that value into formula I.7.

(29) Group I High Gain ζRH and Normal Gain ζRN

Calculate the attenuation ratios ζ_{RH} and ζ_{RN} by substituting the values of R F2 and RF3 into equations I.7 and I.8.

(30) Bode Plot Construction

Compute the open loop transfer function G(s) and construct the Bode plot.

(31) Analysis

Determine if the system is suitable from the open and closed loop characteristics.

(32) Analysis to determine TRmin and TRmax

Repeat the analysis of items (30) and (31) for group I TRmin and TRmax.

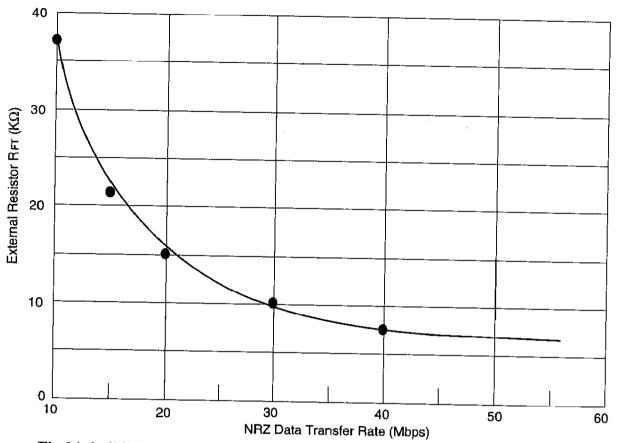


Fig 24. 2 T/I Converter Circuit External Resistor RFT vs NRZ Data Transfer Rate

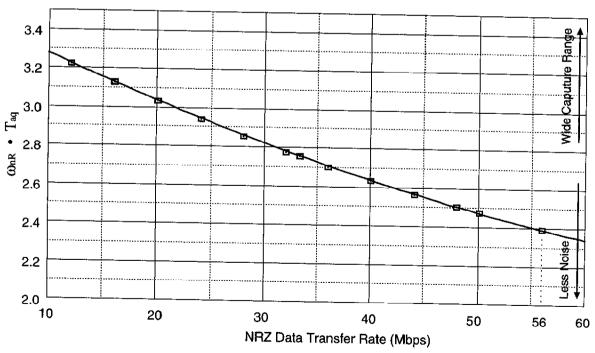


Fig 24. 3 ω_{nR} • T_{aq} vs NRZ Data Transfer Rate (R-PLL)

25. Calculation example of HD153035F R-PLL Constants

Transfer rate; 28Mbps, 56Mbps 2 zones

(1) RFVCO

Oscillation frequency (fo)= 36 MHz at R $_{FVCO}$ = 3 $k\Omega$ • • • 24 Mbps

At 28 Mbps case, fo = 42 MHz

42 MHz x Revco = 36 MHz x 3 k Ω

Revoc = $2.57 \text{ k}\Omega$

∴ RFvco = 2.55K Ω •••• foscr = 42.4 MHz

Error of oscillation frequency is

(fosc - fo)+ fo = $0.84 \% \le 5 \%$

(2) $RFT = 11K\Omega$

See Fig. 24.2

(3) VCO Gain KOR

Kor 28 = 1.536 x 10
$$\sqrt[9]{\frac{32}{2.55 \times 10^3}}$$
 = 172.1 Mrad/s•V

Kor 56 = 1.536 x 10
$$\sqrt[9]{\frac{63}{2.55 \times 10^3}}$$
 = 241.4 Mrad/s • V

(4) Charge Pump Current Ica

$$RFC = 5.1 \text{ K}\Omega$$

$$I_{CR 56} = \frac{2.5 \times 10^4}{5.1 \times 10^3} \cdot \frac{P}{8} \le 5 \text{ mA}$$

$$lcr 56 = 4.9 mA (P=8)$$

(5) T/I Current ITR

ITR 56 =
$$\frac{4.9}{6 \cdot (16 \cdot 1)}$$
 = 54.4 µA

$$RFT = 11 K\Omega$$

: ITR 56 = 57.9
$$\mu$$
A (N=63,L=3)

(6) ω nRH • Taq 56 = 2.4

$$T_{aq 56} = 0.57 \mu s$$
 (6 bytes x 2/3)

 ω nRH = 4.21 Mrad/s

$$\omega_{ nRH 56} = \sqrt{\frac{\text{Kor 56} \cdot \left(\frac{\text{ICR 56}}{6} + \text{ITR 56}\right)}{\pi \cdot \text{CF1}}}$$

$$4.21 \times 10^{6} = \sqrt{\frac{241.4 \times 10^{6} \cdot \left(\frac{4.9 \times 10^{-3}}{6} + 57.9 \times 10^{-6}\right)}{\pi \cdot \text{CF1}}}$$

$$C_{F1} = 3792 pF$$

$$CF2 = CF1 + 45 = 84 pF$$

$$\therefore$$
 CF1 = 3900 pF, CF2 = 82 pF

$$\omega_{\text{ nRH 56}} = \sqrt{\frac{241.4 \times 10^{6} \cdot \left(\frac{4.9 \times 10^{-3}}{6} + 57.9 \times 10^{-6}\right)}{\pi \times 3900 \times 10^{-12}}} = 4.15 \text{ Mrad/s}$$

$$\omega$$
 nRN 56 = $\sqrt{\frac{241.4 \times 10^{6} \times 57.9 \times 10^{-6}}{\pi \times 3900 \times 10^{-12}}}$ = 1.07 Mrad /s

(7)
$$\zeta_{RN 56} = 1.0$$
 , $\zeta_{RH 56} = 0.8$

RF₂ = 1.0 + { (3900 x 10⁻¹² + 82 x 10⁻¹²) + 2 x 1.07 x 10⁻⁶} = 469.4
$$\Omega$$

RF₃ = 122 Ω

$$\therefore \ R_{F2} = 470 \ \Omega \ , \quad R_{F3} = 120 \ \Omega$$

$$\zeta_{RN \ 56} = 1.0 \ , \quad \zeta_{RH \ 56} = 0.79$$

(8)
$$\omega n \cdot T_{aq 28} = 2.86$$

$$T_{aq 28} = 1.14 \,\mu s$$
 (6 bytes x 2/3)
 $\omega_{nH 24} = 2.51 \,Mrad/s$

(9) Charge Pump Current LCR

ICR 28 =
$$\frac{6\pi \cdot C_{F1} \cdot \omega_{nH}^2}{K_{OR 28}} \cdot \frac{g_{G-1}}{g_{G}} = 2.52 \text{ mA}$$

$$\therefore$$
 ICR 28 = 2.45 mA (P= 4)

(10) T/I Current ITR

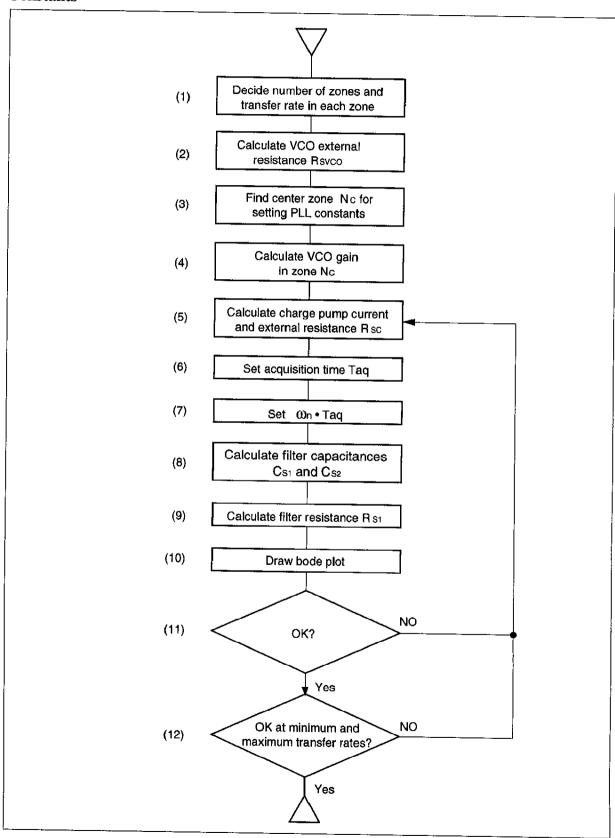
$$IT 28 = 2.45 \div 6 \div (16 - 1) = 27.2 \,\mu A$$

$$\therefore$$
 IT 28 = 29.4 μA (N = 32, L = 3), ω nH 28 = 2.47 Mrad/s, ω nN 28 = 0.64 Mrad/s

(11) $\zeta RN 28 = 1.0$, $\zeta RH 28 = 0.8$

RF0 = 820
$$\Omega$$
 , RF1 = 200 Ω
 ζ RN 28 = 1.04, ζ RH 56 = 0.79

26. Flowchart for Setting Encode Clock Generator's Frequency Synthesizer (W-PLL) Constants



27. Flowchart Explanation (W-PLL)

(1) Decide the number of zones and transfer rate in each zone

The HD153035F uses a frequency synthesizer to generate the reference clock, so the value of the transfer rate is quantized. If the lowest rate corresponds to N=16, the available rates are given by the formula:

TRN = TRmin, $16 \le N \le 63$

where,

TR N: Transfer rates in different zones

TRmin: Minimum transfer rate (innermost track)

(2) Calculate VCO external resistance R svco

Use equation (II.1) to calculate the external resistance R svco that makes the VCO oscillate at 1.5 times the minimum transfer rate (N=16)

(3) Find center zone (TRcen)

Calculate the midpoint (TRcen) between the minimum transfer rate (TRmin) and maximum transfer rate (TRmax), and from the zones selected in step (1), find the value of N (N c) that comes closest to TRcen.

(4) VCO gain Kow

Use equation (II.2) to calculate the VCO gain ζ in the center zone (N=N c)

(5) Charge pump current I cw

Select the charge pump current within the following range:

Calculate the necessary external resistance R sc from equation (II.4).

(6) Setting phase-lock acquisition time Taq

Decide the phase-lock acquisition time Taq, considering the change in characteristic frequency from zone to zone and the head seek time.

(7) Setting (ω_n • T_{aq})

Decide $(\omega_n \bullet T_{aq})$ the end of the phase-lock acquisition.

(8) Filter capacitances Cs1 and Cs2

Decide the phase-lock acquisition time Taq, considering the charge in characteristic frequency from zone to zone and the head seek time. The value used in this data sheet is:

$$Taq = 0.1$$
 (ms)

The following formula gives an estimate of the acquisition time:

$$\omega_n w \cdot Taq = 2.25$$

Substitute the values of K cw and low into equation (II.5) and combine this with the formula above to calculate the filter capacitance C s_1 . To suppress jitter and allow enough phase margin, the following value is recommended for C s_2 :

$$C_{S2} = \frac{1}{45} \cdot C_{S1}$$

(9) Filter resistance R s1

To ensure loop stability, set the attenuation to approximately:

$$\zeta$$
 nw = 1.0

Substitute this value into equation (I.6) to calculate the filter resistance R s1.

(10) Bode plot

Calculate the open-loop transfer function G(s) and draw a Bode plot.

(11) OK?

Decide whether the open -loop and closed -loop characteristics are satisfactory.

(12) OK at TRmin and TRmax?

Repeat steps (8) and (9) for the minimum and maximum transfer rates.

28. Calculation example of HD153035F W-PLL Constants

NRZ transfer rate; 28Mbps, 56Mbps (2 zones)

(1) Oscillation frequency $fow = 42MHz (28 \times 1.5), N=32$

Rsvco =
$$\frac{(6.975 \times 10^9) \cdot 32}{\text{fow}}$$
 = 5.31 kΩ

∴ Rsvco = 5.24 k
$$\Omega$$
 ••••• foscw = 42.60 MHz

Error of oscillation frequency is I (foscw - fow) \div fow I = 1.4 % \le 5 %

(2) VCO gain Kow

Kow 28 = 1.056 x 10
$$^{9}\sqrt{\frac{32}{5.24 \times 10^{3}}}$$
 = 82.5 Mrad / s • V
Kow 56 = 1.056 x 10 $^{9}\sqrt{\frac{63}{5.24 \times 10^{3}}}$ = 115.8 Mrad / s • V

(3) Charge Pump Current Tow

$$Rcs = 20K\Omega$$

lcw
$$_{28} = \frac{5.3}{20 \times 10^3} (1 + \frac{3}{8}) = 364.4 \mu A \text{ (NC=3)}$$

lcw
$$_{56} = \frac{5.3}{20 \times 10^3} (1 + \frac{7}{8}) = 496.9 \,\mu\text{A} \quad (NC=7)$$

(4) Cs1, Cs2

$$\omega$$
n • Taq = 2.25

(
$$\omega$$
 n = 22.5 Krad / s) (taq = 0.1 ms)

$$22.5 \times 10^{3} = \sqrt{\frac{81.7 \times 10^{6} \times 364.4 \times 10^{-6}}{2\pi \cdot 128 \cdot \text{Cs}_{128}}}$$

$$22.5 \times 10^{3} = \sqrt{\frac{114.6 \times 10^{6} \times 496.9 \times 10^{-6}}{2\pi \cdot 255 \cdot Cs_{1.56}}}$$

$$\frac{\text{Cs1}}{\approx 75000 \text{ pF}} = (76483 + 73432) / 2 = 74958$$

$$Cs2 = \frac{1}{45} \cdot Cs1 = 1667$$

$$RS1 = 1$$

(5) Rs₁

Attenuation
$$\zeta_{nw} = 1$$

$$\zeta_{\text{nw}} = \frac{(75000 + 1600) \times 10^{-12}}{2} \cdot \text{Rs}_1 \cdot \omega_{\text{nw}}$$

$$\text{Rs}_1 = 1 + \left\{ \frac{(75000 + 1600) \times 10^{-12}}{2} \times 22.0 \times 10^3 \right\} = 1187 \Omega$$

$$\omega$$
 nw 28 = 22.22 Krad/s, ζ nw 28 = 1.021

$$\omega$$
 nw 56 = 21.77 Krad/s, ζ nw 56 = 1.000

29. Setting value of M and N1 for R-PLL and W-PLL

$$f_{1-7} \text{ (1-7 clock frequency)} = \frac{OSCCLK}{M} \times N1$$

$$Errfw = \frac{|f_{1-7} - foscw|}{foscw} \le 5 \%$$

$$ErrfR = \frac{|f_{1-7} - foscR|}{foscR} \le 5 \%$$

example : OSCCLK = 21 MHz, RFVCO =
$$2.55 \text{ k}\Omega$$
, RSVCO = $5.24 \text{ k}\Omega$, f $_{1-7}$ = 42 MHz , 63 MHz, 84 MHz M = 64 , N1 = 128 , N = 32 •••• f $_{1-7}$ = 42.0 MHz, foscw = 42.60 MHz, foscR = 42.35 MHz Errfw = 1.4 % < 5 % ErrfR = 0.8 % < 5 % M = 64 , N1 = 192 , N = 48 •••• f $_{1-7}$ = 63.0 MHz, fosc = 63.89 MHz, foscR = 63.53 MHz Errfw = 1.4 % < 5 % ErrfR = 0.8 % < 5 % M = 63 , N1 = 252 , N = 63 •••• f $_{1-7}$ = 84.0 MHz, fosc = 83.86 MHz, foscR = 83.38 MHz Errfw = 0.2 % < 5 % ErrfR = 0.7 % < 5 %

30. Example of HD153035F PLL's external parts (28/42/56Mbps)

OSCCLK = 21 MHz

 $R_{F0} = 820 \Omega$

(A) R-PLL

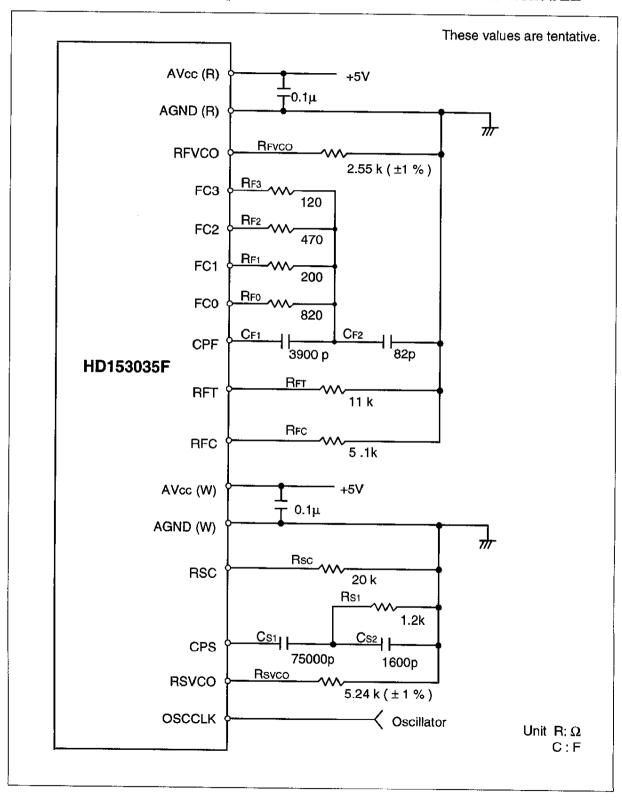
RFvco = $2.55 \text{ k}\Omega$	Register Value							
RFC = $5.1 \text{ k}\Omega$ RFT = $11 \text{ k}\Omega$ CF1 = 3900 pF CF2 = 82 pF RF3 = 120Ω		28Mbps	42 Mbps	56 Mbps				
	VFC	1000 0000	1100 0000	1111 1100				
	GAC	0 <u>001 1011</u>	0 <u>110 1011</u>	0 <u>111 1011</u>				
$RF2 = 470~\Omega$								
$R_{F1} = 200 \Omega$								

(B) W-PLL

Rsvco = $5.24 \text{ k}\Omega$ Rcs = $20 \text{ k}\Omega$		28Mbps	42 Mbps	56 Mbps
Cs1 = 75000pF	VFC	1000 0000	1100 0000	1111 1100
$Cs_2 = 1600pF$ $Rs_1 = 1.2 k\Omega$	SGC	0000 0 <u>011</u>	0000 0 <u>101</u>	0000 0 <u>111</u>
1101 - 1.2 Naz	PSC	0 <u>010 0000</u>	0 <u>010 0000</u>	0 <u>011 1111</u>

Register Value

31. Example of External Components Connected to the Read PLL and Write PLL



32. 1-7 ENDEC

Encoder and Decoder

The encoder converts an NRZ signal to a (1,7) encoding, and the decoder converts a (1,7) signal back to an NRZ signal. The conversion table is shown in Table 32.1.

The NRZ signal is encoded after being inverted. The inverted \overline{NRZ} signal is encoded according to the conversion rules shown in fig. 32.1.

Therefore the disk controller should input the sequence "0000..." in the sync region. This will be converted to the (1,7) encoding 3T pattern "10010 0...".

The NRZ signal is encoded after being

inverted.

For example, if the \overline{NRZ} data 00 is to be (1,7) encoded, it is first inverted to 11.

Next, since the last bit of the previous conversion result A (100) was 0, and the next state of the NRZ data C is 01 (\overline{C} =10), the NRZ data B (00) is converted to the (1,7) code 100.

In decoding the (1,7) code I (=100) to NRZ data (see Fig 32.2), since the previous data H was 100 and the next data J is 010, the decoding table gives 1 1 as the $\overline{\text{NRZ}}$ data. Inverting this gives the NRZ data 00, which is then output.

Table 32.1 Encoding Table (NRZ to (1,7) Code)

	Last Bit of the Previous (1,7)		NRZ Da	ta Bit				
No.	Code	Current	(D1,D2)	Next	(D3,D4)	(1,7) Code Bits (C2,C3,C4)		
1	0	1	0	0	Х	1	0	1
2	0	1	0	1	×	0	1	0
3	0	1	1	0	0	0	1	0
4	0	1	1	0	0	1	0	0
5	0	0	0	0	Х	0	0	1
6	0	0	0	1	Х	0	0	0
7	0	0	1	0	Х	0	0	1
8	0	0	1	1	X	0	0	0
9	1	0	0	0	Х	0	0	1
10	1	0	0	1	Х	0	1	0
11	1	0	1	0	0	0	1	0
12	1	0	1	0	0	0	0	0

0 0: Anything other than 0 0

X : Don't care

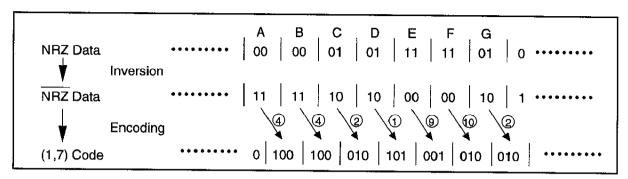


Fig. 32.1 Shows an Example of NRZ to (1,7) Code Conversion.

Table 32. 2 Decoding Table ((1,7) Code to NRZ)

	(1,7) Code Bits											
No	Р	reviou	s	<u> </u>	Current			Next			NRZ Data Bit	
1	X	1	0	0	0	0	Х	X	Х	0	0	
2	X	0	0	0	0	0	X	Х	Х	0	1	
3	Х	Х	Х	1	0	0	Х	Χ	Х	1	1	
4	X	Х	0	0	1	0	0	0	Х	1	0	
5	X	Х	0	0	1	0	0	0	X	1	1	
6	Х	X	X	1	0	1	Х	Х	X	1	0	
7	Х	0	0	0	0	1	Х	Χ	Х	0	1	
8	Х	1	0	0	0	1	Х	X	Х	0	0	
9	Х	Х	1	0	0	. 1	Х	Χ	Х	0	0	
10	Х	Х	1	0	1	0	0	0	Х	0	0	
11	Х	Х	1	0	1	0	0	0	Х	0	1	
12	Х	Х	1	0	0	0	Х	Χ	Х	0	1	

00: Anything other than 00

X : Don't care

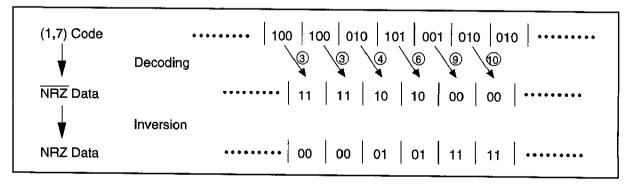


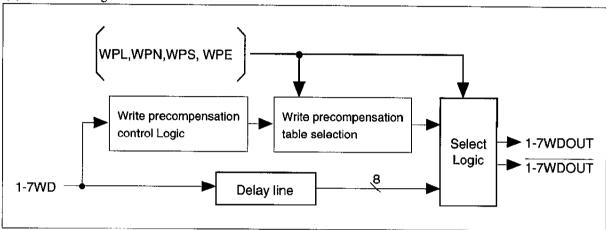
Fig. 32.2 (1,7) Code to NRZ Decoding Example

33. Write Precompensation Circuit

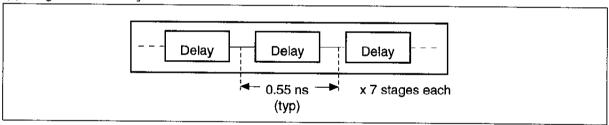
The HD153035F has a built-in synchronous write precompensation circuit, and the 4 matrix delay levels from the write precompensation table shown

below can be selected independently for the EARLY and LATE sides. Each delay group of the table can select delay value independently.

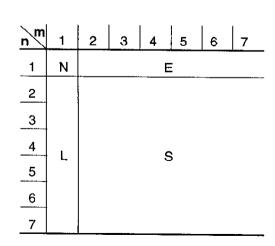
(1) Circuit Configuration



(2) Programmable Delay Line



(3) Table



		n			m						
1	0	• • •	0	1	0	• • •	0	1	0		
Pr	evio	us		C	ırren		Ne	ext			

- n: The number of zero's between the current1 bit and the previous 1 bit
- m: The number of zero's between the current 1 bit and the next 1 bit

The precompensation delay time for each the 4 matrix entries in the precompensation table (see Table) can be set independently.

The delay time (8 levels) is selected by the each part of register.

34. Idle / Servo input pin for power saving:

With the mode control register(PCN), there are four different modes of operation as shown: 11 = Sleep, 10 = Power Save, 00 = Normal (full power). The modes are defined as followed:

- a) When bits 5.4 = 00: Normal mode. All circuitries are powered.
- b) When bits 5,4 = 11: Sleep mode. Everythings powered down except the I/O and the logic section of the chip.
- c) When bits 5,4 = 10 : Power Save mode. In this mode, the Idle/Servo pin will select which of the two power save modes to be used. If Idle = 1 then Idle mode is selected and all modules will be powered down except for the I/O, logic, and the bias circuitries.. If Idel/Servo = 0 then Servo mode will be selected and all blocks will be kept on except the clock syncthesizer (WR PLL) and the synchronizer (RD PLL).

	Mode	A14 D5,4	I/S pin	I/O	Logic	Bias	RD PLL	WR PLL	AGC	AF	RPD	PH
_	Normal	00	X	ON	ON	ON	ON	ON	ON	ON	ON	ON
Power	Servo	10	0	ON	ON	ОИ			ON	ON	ON	ON
Save	Idle	10	1	ON	ON	ON						
	Sleep	11	Х	ON	ON							

35. Recommendation for PCB layout

To reduce Ground noise for proper chip operation, the following PCB board layout is recommended:

- (1) Dedicate 1 layer for Ground plane.
- (2) Divide the ground plane into 4 segments as show fig. 35.1
- (3) System ground is connected Master GND.

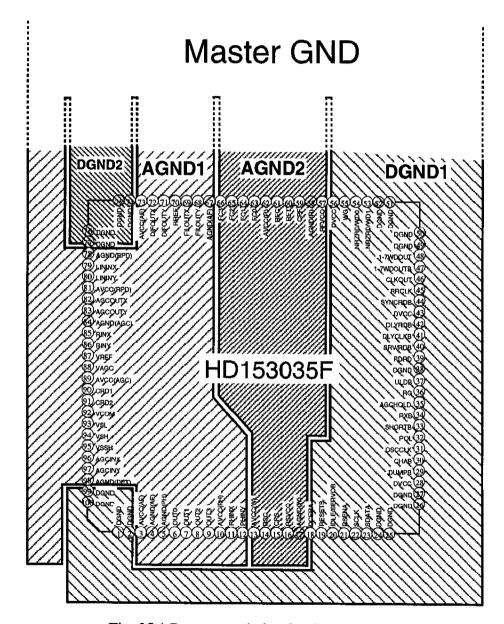


Fig. 35.1 Recommendation for Ground layout

36. Absolute Maximum Ratings (Ta=25 °C)

Description	Symbol	Ratings	Unit	Applicable pins	
Supply voltage	Vcc	7	V	DVcc, AVcc	
Input voltage	Vı	- 0.3 to 5.5	٧	Note1	
Output voltage	Vo	5.5	٧	Note2	
Operating temperature	Topr	0 to 70	°C		
Storage temperature	Tstg	- 55 to + 125	°C		

Note1: OSCCLK, RESET, IDLE/SERVO, RSENA, SCLK, SDATA, DUMP, CHA, SHORT, RX, AGCHOLD, RG, SRV/RD, NRZRD/WD0(Write mode), NRZRD/WD1(Write mode), WG, DCERA Note2: SDATA, POL, ULD, PDRD, DLYCLK, DLYRD, SYNCRD, RRCLK, CLKOUT, 1-7WDOUT, 1-7 WDOUT, NRZRD/WD0(Read mode), NRZRD/WD1(Read mode)

37. Electrical Characteristics (Ta=0 to + 70 °C, $Vcc = 5.0V \pm 10\%$ unless otherwise noted)

General Item	Symbol	min	typ	max	unit	conditions	Applicable pins
Power supply voltage	Vcc	4.5	5	5.5	V		Note4
Operation temperature	Ta	0	25	70	°C		
NRZ transfer rate		15		56	Mbps		
Power supply current	Icc		850		mW	at 56Mbps, R/W 20% Idle/Servo mode 80%	Note4
TTL 'H' level intput voltage	ViH	2.2			V	Vcc=4.5V	Note1
TTL 'L' level intput voltage	VIL			8.0	V	Vcc=4.5V	Note1
TTL 'H' level output voltage	Vонт	2.4			V	loн=-400μA, Vcc=4.5V	/ Note2
TTL 'L' level output voltage	Volt			0.5	٧	lou=4mA, Vcc=4.5V	Note2
ECL 'H' level output voltage	VOHE	Vcc -0.95	Vcc -0.8		٧	Ta=25°C, RL=510Ω	Note3
ECL 'L' level output voltage	VOLE		Vcc -1.8	Vcc -1.6	٧	Ta=25°C, RL=510Ω	Note3
Input ourrent	lін			20	μΑ	Vcc=5.5V,Vi=2.7V	Note1
input current	lıL			-400	μА	Vcc=5.5V,Vi=0.4V	Note1
Output shorted current	los	-20		-120	mA	Vcc=5.5V	Note2
Input clamp voltage	Vık			-1.5 V	V	Vcc=4.5V,Iон=-18mA	Note1

Note1: OSCCLK,RESET,IDLE/SERVO,RSENA,SCLK,SDATA,DUMP,CHA,SHORT,RX,AGCHOLD,RG, SRV/RD,NRZRD/WD0(Write mode),NRZRD/WD1(Write mode),WG,DCERA

Note2: SDATA,POL,ULD,PDRD,DLYCLK,DLYRD,SYNCRD,RRCLK,CLKOUT,1-7WDOUT(TTL), 1-7WDOUT(TTL), NRZRD/WD0(Read mode),NRZRD/WD1(Read mode)

Note3: 1-7WDOUT(ECL),1-7WDOUT(ECL)

Note4: DVcc,AVcc(PH),AVcc(W),AVcc(R),AVcc(AF),AVcc(AGC),AVcc(RPD)

38. Encoder/Decoder(Ta=25°C, Vcc=5V,56Mbps)

Item	Symbol	min	typ	max	unit	conditions	Applicable pins
NRZRD set-up time (serial)	tsnrs	9.0			ns		NRZRD/WD0
NRZRD set-up time (parallel)	tsnrp	16.0			ns		NRZRD/WD0,1
NRZRD hold time (serial)	thnrs	8.0			ns		NRZRD/WD0
NRZRD hold time (parallel)	thnrp	21.0			ns		NRZRD/WD0,1
NRZWD set-up time (serial)	tsnws	8.0			ns		NRZRD/WD0
NRZWD set-up time (parallel)	tsnwp	17.0			ns		NRZRD/WD0,1
NRZWD hold time (serial)	thnws	0			ns		NRZRD/WD0
NRZWD hold time (parallel)	thnwp	0			ns		NRZRD/WD0,1
RRCLK high time	T/2(H)	14.0			ns		RRCLK
RRCLK low time	T/2(L)	14.0			ns		RRCLK
Decode time	too		15	15	RRCLK		NRZRD/WD0
Encode time	t ed		12.5	14.5	RRCLK		1-7WDOUT, 1-7WDOUT
Write Precomp time step		0.28	0.55	0.82	ns	Not tested	
Write Precomp time width		± 2.0	± 3.85	± 5.7	ns	± 7steps	

39. Register (Ta=25°C, Vcc=5V)

Item	Symbol	min	typ	max	unit	conditions	Applicable pins
RSENA "L" time	tel	1650			ns		RSENA
RSENA "H" time	te⊬	50			ns		RSENA
RSENA falling edge to the first SCLK rising edge	t efsr	50			ns		SCLK
SDATA set up time	tops	10			ns		SDATA
SDATA hold time	tсон	10		••••	ns		SDATA
The last SCLK falling edge to RSENA rising edge	tsfer	50			ns		RSENA
SCLK cycle time	too	100			ns		SCLK
SCLK "H" time	tсн	40	•		ns	- 4 - 1	SCLK
SCLK "L" time	t cl	40			ns		SCLK
SDATA output delay	tcdd			20	ns		SDATA
SDATA output hold time	t EDH	5			ns		SDATA

40. Synchronizer (Ta=25°C, Vcc=5V)

Item	Symbol	min	typ	max	unit	conditions
Read VCO center frequency 1	fvco1	39.9	42	44.2	MHz	RFVCO=2.47k, Register VFC=7B Hex
Phase lock acquisition time 1				6	Byte	6 NRZ bytes period at 28Mbps
Capture range 1		±15			%	at 28Mbps
Lock range 1		±15			%	at 28Mbps
Read VCO gain 1		129	172	215	Mrad / sec •V	RFVCO=2.47k, Register VFC=7B Hex
Read VCO upper limit clamping frequency 1			55		MHz	RFVCO=2.47k, Register VFC=7B Hex
Read VCO lower limit clamping frequency 1			30		MHz	RFVCO=2.47k, Register VFC=7B Hex
Read VCO center frequency 2	fvco2	79.9	84	88.3	MHz	RFVCO=2.47k, Register VFC=F6 Hex
Phase lock acquisition time 2				6	Byte	6 NRZ bytes period at 56Mbps
Capture range 2		±15			%	at 56Mbps
Lock range 2		±15			%	at 56Mbps
Read VCO gain 2		178	236	296	Mrad / sec •V	RFVCO=2.47k, Register VFC=F6 Hex
Read VCO upper limit clamping frequency 2		_	109	_	MHz	RFVCO=2.47k, Register VFC=F6 Hex
Read VCO lower limit clamping frequency 2			55		MHz	RFVCO=2.47k, Register VFC=F6 Hex
Window margin loss		0		3	ns	at any data rate
Window adjust step		0.34	0.67	1.0	ns	31 steps, Not tested
Window adjust width		+5.5 -5.9	+10.0 -10.7	+14.5 -15.5	ns	+15 step, -16step
Window fine adjust width		0.12	0.25	0.5	ns	total 4 steps
Read VCO maximum oscillate frequency		90	108	_	MHz	RFVCO=1k, Register VFC=80Hex
Decode window center accuracy		-3 -2		3 2	ns	at 28Mbps at 56Mbps
T/I offset accuracy		-6 -15		6 1 5	μs	at 28Mbps at 56Mbps
C/D offset accuracy		-15		+15	%	at GAC=20Hex
Oscillation start voltage				4.0	٧	Ta=25°C fosc ≧100kHz

41. Synthesizer (Ta=25°C, Vcc=5V)

Item	Symbol	mln	typ	max	unit	conditions
Write VCO center frequency	fwvco	80.0	84.0	88.3	MHz	RSVCO=5.1k, Register VFC=F6 Hex
Write VCO upper limit clamping frequency			100.9		MHz	RSVCO=5.1k, Register VFC=F6 Hex
Write VCO lower limit clamping frequency			67.3		MHz	RSVCO=5.1k, Register VFC=F6 Hex
Phase lock acquisition time				1	ms	tested at 28Mbps, 56Mbps
Capture range		±10			%	tested at 28Mbps, 56Mbps
Lock range		±10			%	tested at 28Mbps, 56Mbps
VCO frequency step		_	1.0	_	%	at fmax / fLow = 2.55
VCO gain		84	115	140	Mrad / sec • V	RSVCO=5.1k, Register VFC=F6 Hex

42. RPD & PH (Ta=25°C, Vcc=5V)

Item	C, VCC=3	v <i>)</i> min	typ	max	unit	conditions	Applicable pins
Max peak-peak Input signal				2.0	Vpp	differential inputs	PHINX/Y
PDRD pulse width		4.5	9	13.5	ns	at 40Mbps, PW[1:0]=00)
PDRD pulse rise time	tr	0.5	2	4	ns	CL=15pF,20%-80%,	Not tested
PDRD pulse fall time	tf	0.5	2	4	ns	CL=15pF,80%-20%,	Not tested
P/H output voltage swing		2.0	2.3	2.6	٧	fin=6.5MHz, Vin=2Vpp	**
P/H output leakage current		-0.2	0	+0.2	μΑ		OUT0 ~ OUT3
P/H Channel Offset		-50		+50	mV		OUT0 ~ OUT3
P/H Reference Voltage			VCOM x 25%		٧	PHINX/Y=0Vpp	OUT0 ~ OUT3
P/H Discharge time	tosca			2.0	μS	Соито ~ Соитз =1000pF	OUT0 ~ OUT3
P/H Sampling time (CHA = "L" time)	t spl	2.0			μS		CHA
CHA Switching time	tswr	200			ns		CHA

^{** :} differential input for PHINX and PHINY.

43. Active Filter (Ta=25°C, Vcc=5V)

Item	Symbol	min	typ	max	unit	conditions
Filter cutoff frequency	fc	5		25	MHz	
fc Accuracy	fca	- 15		+15	%	
Filter boost level	Fb	0	***************************************	10	dB	
Filter boost Accuracy	Fba	- 1		1	dB	Fb = 10dB
Output dynamic range				1.7	V pp	diff. outputs, THD < 2%
Output noise(normal)			3	5.5	mVRms	Not tested
Output noise(differential)			6	10	mVRms	Not tested
Group delay variation (0)			± 3		%	Fb=0, condition 1
Group delay variation (1)			± 3		%	Fb=10, condition 1
Power noise rejection	PSRR		- 45		dB	Not tested

Condition 1: fc = 18MHz, range = 0.2fc to fc, measured from AGCOUTX/Y to FILOUTX/Y.

44. AGC (Ta=25°C, Vcc=5V)

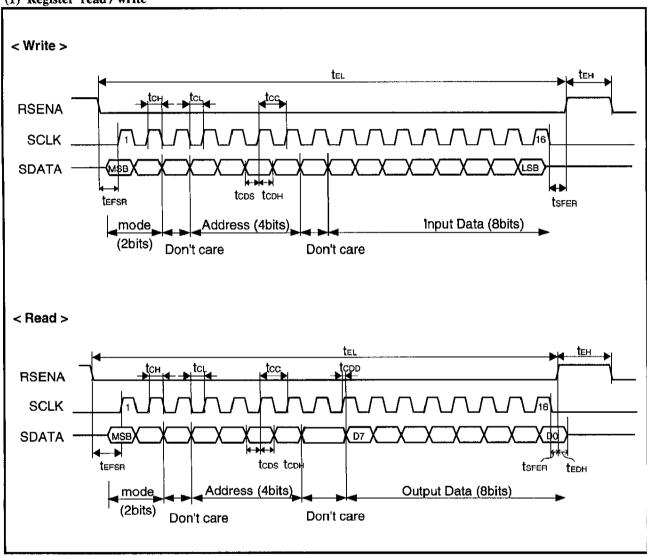
Item	Symbol	<u>min</u>	typ	max	unit	conditions
AGC max gain		(39)	43		dB	RINX/Y to FILOUTX/Y
AGC min gain				0	V/V	
Input dynamic range		20		200	mV	Distortion <2%
Band width(-3dB)	Bw	50			MHz	
Output DC offset	Voff		100	200	m۷	AGCOUTX/Y
Input noise(max gain)			5	15	nV/√Hz	Not tested
Write to read recovery time	twrr		1	2	μs	write(RX=L) to read cycle
Read recovery time	trr			5	μs	recovery from max gain

45. P/H of servo mode (Ta=25°C, Vcc=5V)

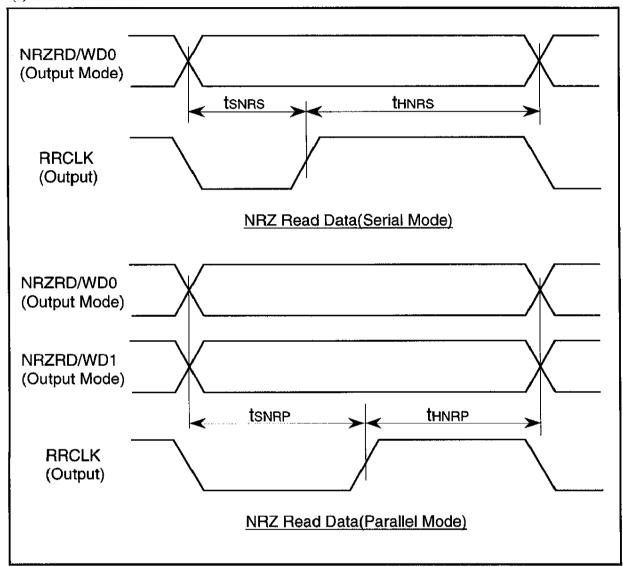
conditions
CRD=3300pF
Соито~Соитз=1000рF

46. AC Timing Chart





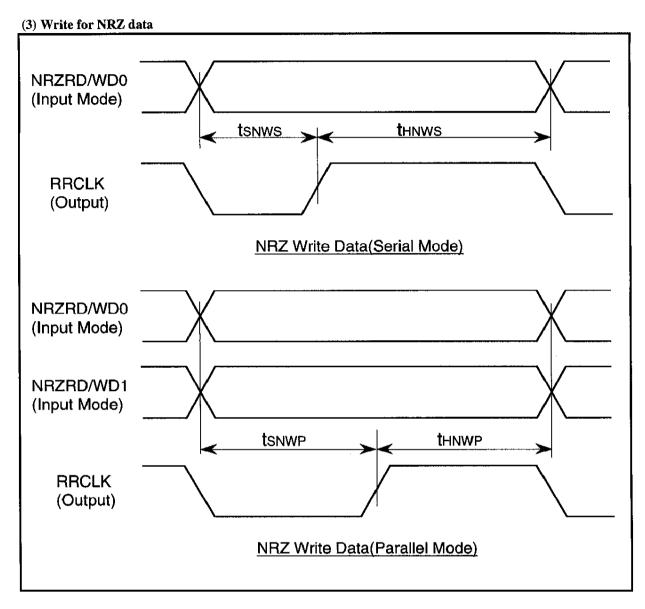
(2) Read for NRZ data



Note1: When data transfer rate is 40Mbps(Serial Mode),NRZ and RRCLK Output is 40MHz. RRCLK clock duty "L":"H" =1:2.

When data transfer rate is 40Mbps(Parallel Mode),NRZ and RRCLK Output is 20MHz. RRCLK clock duty "L":"H" =1:1

We recommend that more than 40Mbps, please select the "Parallel" mode.

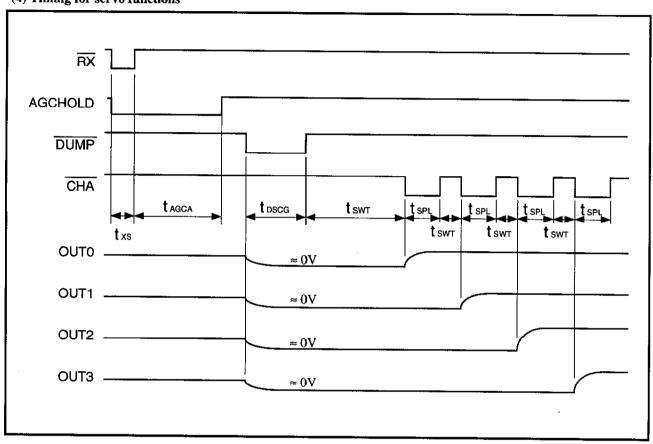


Note2: When data transfer rate is 40Mbps(Serial Mode), RRCLK Output is 40MHz . RRCLK clock duty "L":"H" =1:2.

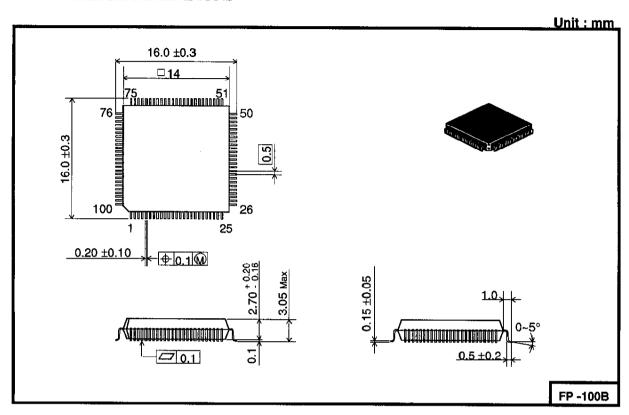
When data transfer rate is 40Mbps(Parallel Mode), RRCLK Output is 20MHz . RRCLK clock duty "L":"H" =1:1

We recommend that more than 40Mbps, please select the "Parallel" mode.

(4) Timing for servo functions



47. PACKAGE DIMENSIONS



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